

SCHOOL OF ELECTRONICS ENGINEERING

M. Tech VLSI Design

(M.Tech MVD)

Curriculum

(2020-2021 admitted students)

VISION STATEMENT OF VELLORE INSTITUTE OF TECHNOLOGY

Transforming life through excellence in education and research. MISSION STATEMENT OF VELLORE INSTITUTE OF TECHNOLOGY

World class Education: Excellence in education, grounded in ethics and critical thinking, for improvement of life.

Cutting edge Research: An innovation ecosystem to extend knowledge and solve critical problems.

Impactful People: Happy, accountable, caring and effective workforce and students.

Rewarding Co-creations: Active collaboration with national & international industries & universities for productivity and economic development.

Service to Society: Service to the region and world through knowledge and compassion.

VISION STATEMENT OF THE SCHOOL OF ELECTRONICS ENGINEERING

To be a leader by imparting in-depth knowledge in Electronics Engineering, nurturing engineers, technologists and researchers of highest competence, who would engage in sustainable development to cater the global needs of industry and society.

MISSION STATEMENT OF THE SCHOOL OF ELECTRONICS ENGINEERING

- Create and maintain an environment to excel in teaching, learning and applied research in the fields of electronics, communication engineering and allied disciplines which pioneer for sustainable growth.
- Equip our students with necessary knowledge and skills which enable them to be lifelong learners to solve practical problems and to improve the quality of human life.

M. Tech. VLSI Design

PROGRAMME EDUCATIONAL OBJECTIVES (PEOs)

1. Graduates will be engineering practitioners and leaders, who would help solve industry's technological problems.

2. Graduates will be engineering professionals, innovators or entrepreneurs engaged in technology development, technology deployment, or engineering system implementation in industry.

3. Graduates will function in their profession with social awareness and responsibility.

4. Graduates will interact with their peers in other disciplines in industry and society and contribute to the economic growth of the country.

5. Graduates will be successful in pursuing higher studies in engineering or management.

6. Graduates will pursue career paths in teaching or research.

M. Tech VLSI Design

PROGRAMME OUTCOMES (POs)

PO_01: Having an ability to apply mathematics and science in engineering applications.

PO_02: Having an ability to design a component or a product applying all the relevant standards and with realistic constraints, including public health, safety, culture, society and environment

PO_03: Having an ability to design and conduct experiments, as well as to analyse and interpret data, and synthesis of information

PO_04: Having an ability to use techniques, skills, resources and modern engineering and IT tools necessary for engineering practice

PO_05: Having problem solving ability- to assess social issues (societal, health, safety, legal and cultural) and engineering problems

PO_06: Having adaptive thinking and adaptability in relation to environmental context and sustainable development

PO_07: Having a clear understanding of professional and ethical responsibility

PO_08: Having a good cognitive load management skills related to project management and finance

PROGRAMME SPECIFIC OUTCOMES (PSOs)

On completion of M. Tech. (VLSI Design) programme, graduates will be able to

PSO1: Apply advanced concepts in Physics of semiconductor devices to design VLSI Systems.

PSO2: Design ASIC and FPGA based systems using industry standard tools.

PSO3: Solve research gaps and provide solutions to socio-economic, and environmental problems.

Category-wise Credit distribution

Category	Credits
University core (UC)	27
Programme core (PC)	19
Programme elective (PE)	18
University elective (UE)	6
Bridge course (BC)	
Total credits	70

Detailed curriculum

(as given in the student curriculum view – in the order of UC, UE, PC and PE). Courses need not be listed under UE.

University Core - 27 Credits

S.	Course Code	Course Title	L	Т	P	J	C
No							
1.	MAT5009	Advanced Computer	2	2	0	0	3
		Arithmetic					
2.	ENG5001 and	Technical English I and	{0	0	2	0	2
	ENG5002	Technical English II	0	0	2	0}	
	(or) EFL5097	(or) Foreign Language	2	0	0	0	
3.	STS5001	Soft Skills	0	0	0	0	1
4.	STS5002	Soft Skills	0	0	0	0	1
5.	SET5001	SET Project-I	0	0	0	0	2
6.	SET5002	SET Project-II	0	0	0	0	2
7.	ECE6099	Master's Thesis	0	0	0	0	16

University Elective – 6 Credits

S.No	Course Title	LT		Ρ	J	C
1	University Elective [#]	-	-	-	-	6

All courses offered by other M.Tech Programmes / PE of M.Tech (VLSI Design)

Programme Core – 19 Credits

S. Io	Course Code	Course Title	L	Т	Р	J	С
1	ECE5014	ASIC Design	3	0	2	0	4
2	ECE5015	Digital IC Design	3	0	0	4	4
3	ECE5016	Analog IC Design	3	0	2	0	4
4	ECE5017	Digital Design with FPGA	2	0	2	4	4
5	ECE5018	Physics of VLSI Devices	3	0	0	0	3

Programme Electives - 18 Credits

S. No	Course Code	Course Title	L	Т	Р	J	C
1	ECE5019	Computer Aided Design for VLSI	3	0	0	0	3
2	ECE5020	DSP Architectures	2	0	0	4	3
3	ECE5022	VLSI Digital Signal Processing	3	0	0	0	3
4	ECE5023	Memory Design and Testing	3	0	0	0	3
5	ECE5024	IC Technology	3	0	0	0	3
6	ECE5025	System-on-Chip Design		0	0	0	3
7	ECE5026	System Design with FPGA		0	0	4	3
8	ECE5027	Advanced Computer Architecture	3	0	0	0	3
9	ECE5028	Micro Sensors and Interface Electronics	2	0	0	4	3
10	ECE5029	VLSI Testing and Testability	3	0	0	0	3
11	ECE5030	Scripting languages for VLSI design automation	2	0	2	0	3
12	ECE6024	VLSI Verification Methodologies	2	0	0	4	3
13	ECE6025	Low Power IC Design	2	0	0	4	3
14	ECE6026	Mixed Signal IC Design	2	0	0	4	3
15	ECE6027	RFIC Design	2	0	0	4	3
16	ECE6028	Nanoscale Devices and Circuit Design	2	0	0	4	3

Syllabus

Course Code	Course Title	L T P J C
MAT5009	ADVANCED COMPUTER ARITHMETIC	2 2 0 0 3
Pre-requisite	None	Syllabus
Course Objectives		version
The course aimed t		
	be representation of the numbers using redundant and residue num	nber system.
	arious integer arithmetic algorithms, FFT and modular arithmetic	•
	floating-point arithmetic algorithms and its impacts on resulting	
corrective r		
4. Explain CC	ORDIC algorithm for calculating various functions of common int	erest.
1	e implementation aspects of high throughput, low power and faul	t tolerant
arithmetic c	circuits.	
Expected Course The students will b		
	and represent the numbers using redundant and residue numbers	wetem
	and apply various integer arithmetic algorithms.	system.
	and apply various FFT and modular arithmetic algorithms.	
	floating-point arithmetic algorithms, apply it, analyse the impact	s of resulting
	s corrective methods.	8
5. Understand	and apply CORDIC algorithm for calculating various functions of	of common
interest.		
	the implementation aspects of high throughput, low power and fa	ault tolerant
arithmetic c	circuits.	
Module:1 Intro	duction to computer Arithmetic	5 hours
	s and arithmetic. Redundant number systems. Residue number sy	
Module:2 Integ		7 hours
	ptraction. Multiplication. Division. Roots. Greatest Common l	Division. Base
Conversion: Quadr	atic Algorithms, Sub quadratic Algorithms.	
	and Modular Arithmetic	6 hours
_	lassical Representation, Montgomery's Form, Residue Number as, Link with Polynomials. Addition and Subtration. Multiplication	-
0	gomery's Multiplication, McLaughlin's Algorithm, Special	
	er GF (2)[x]. Division and Inversion, Exponentiation, Chine	
Theorem.	······································	
	ing Point Arithmetic	7 hours
	resentation. Floating point operation. Errors and Error control	ol. Precise and
certifiable arithmet	ic.	
		71
	tion Evaluation	7 hours
Arithmetic by Tab	Iethods. The CORDIC Algorithms . Variations in Function Evalu	auon.
Antimetic by Tal	Je Lookup.	
Module:6 Imple	ementations	5 hours
mpic mpic		

Hig	h throug	hput arithmetic, Low powe	r arithmetic, fault	tolerant a	rithmetic	
Mo	dule:7	Error Analysis				6 hours
		ersus Relative Error, Sig	Ū.	Uncertaint	ty in Data. Chop	ping off and
Rou	inding of	ff. Truncation Error. Loss o	f Significance.			
Mo	dule:8	Contemporary issues:				2 hours
				Total	Lecture hours:	45 hours
Tex	t Books					
1.		z Parhami, "Computer Arit sity Press 2015.	hmetic: Algorithn	ns and Ha	rdware Design", (2	2/e) Oxford
2.		P Brent and Paul Zimi sity Press 2010.	merman, "Moder	n Compu	tter Arithmetic",	Cambridge
Ref	erence l	Books				
1.		Vladutiu, "Computer A er 2012.	rithmetic: Algor	ithms an	d Hardware Imp	elementation",
2.	Ulrich	W. Kulisch "Computer Arit	hmetic and Valid	ity: Theor	y, Implementation	, and
	Applica	ations", De Gruyter; 2 editio	on, 2012			
		valuation: Continuous Asse	,	, · ·		
		eminar / Challenging Assig				ideas leading
		for industrial problems, Fin		st (FAT).		
		led by Board of Studies	17-02-2016	Data	05 10 2017	
Арр	brovea b	y Academic Council	No. 47	Date	05-10-2017	

Comme en la	Correct 414	
Course code	Course title Fundamentals of Communication Skills	L T P J C
ENG5001		0 0 2 0 1
Pre-requisite	Not cleared EPT (English Proficiency Test)	Syllabus
		version
Carrier Ohio atia		1.0
Course Objective		• • • • • • • • • • • • • • • • • • • •
	ers learn basic communication skills - Listening, Speaking, Read	ing and writing
2. To help learner	s apply effective communication in social and academic context	
3. To make studer	nts comprehend complex English language through listening and	reading
		0
Expected Course	e Outcome:	
·	tening and comprehending skills of the learners	
	g skills to express their thoughts freely and fluently	
	for effective reading	
Ŭ	cal correct sentences in general and academic writing	
	cal writing skills like writing instructions, transcoding etc.,	
*		
Module:1 Liste	ening	8 hours
Understanding Co	onversation	
Listening to Spee		
Listening for Spe		
Module:2 Spea		4 hours
Exchanging Infor		
	ties, Events and Quantity	
Module:3 Read	ding	6 hours
Identifying Inform	nation	
Inferring Meaning		
Interpreting text		
Module:4 Writ	ing: Sentence	8hours
Basic Sentence St	ructure	
Connectives		
Transformation of	f Sentences	
Synthesis of Sente	ences	
Module:5 Writ	ing: Discourse	4hours
Instructions		
Paragraph		
Transcoding		
		.
		30 hours
	Total Lecture hours:	
Text Book(s)		
,	hris, Theresa Clementson, and Gillie Cunningham. Face2	2face Upper
	Student's Book. 2013, Cambridge University Press.	
Reference Books		
	k .Stepping Stones: A guided approach to writing sentences and I	Paragraphs
,	ion), 2012, Library of Congress.	
2. Clifford A W	hitcomb & Leslie E Whitcomb, Effective Interpersonal and Tean	n

	Communication Skills for Engineers, 2013, John Wiley & Sons, Inc., Hoboken: New Jersey.						
3.	ArunPatil, Henk Eijkman & Ena Bhattacharya, New Media Communication Skills for						
	Engineers and IT Professionals,2012, IGI Global, Hershey PA. Judi Brownell, Listening: Attitudes, Principles and Skills, 2016, 5 th Edition, Routledge:USA						
4.							
5.	John Langan, Ten Steps to Impro Press:USA	ving College Rea	iding Skill	s, 2014, 6 th Edi	tion, Townsend		
6.	Redston, Chris, Theresa Clements	on and Gillie Cu	nningham	Face2face Upp	er Intermediate		
0.	Teacher's Book. 2013, Cambridge						
	Authors, book title, year of publica	ation, edition num	ber press	place			
Moc	le of Evaluation: CAT / Assignmen	t / Quiz / FAT / P	Project / Se	minar			
List	of Challenging Experiments (Ind	licative)					
1.	Familiarizing students to adjective	es through brainst	orming adj	jectives with	2 hours		
	all letters of the English alphabet	U	o add an a	djective that			
	starts with the first letter of their r	name as a prefix.					
2.	Making students identify their pee	d Volume	4 hours				
	during presentation and respond u		•				
		1 1.		1 111	2.1		
3.	Using Picture as a tool to enhance	e learners speaking	g and writh	ng skills	2 hours		
4.	Using Music and Songs as tools	to enhance pronur	ciation in	the target	2 hours		
	language / Activities through VIT	Community Rad	io				
5.	Making students upload their Self	- introduction vid	eos in Vin	neo.com	4 hours		
6.	Brainstorming idiomatic expression	ons and making th	nem use the	ose in to their	4 hours		
	writings and day to day conversat	ion					
7.	Making students Narrate events b		-		4 hours		
	add flavor to their language / Acti						
8	Identifying the root cause of stage	e fear in learners a	nd providi	ng remedies to	4 hours		
0	make their presentation better		.				
9	Identifying common Spelling & S	sentence errors in	Letter Wri	ting and other	2 hours		
10	day to day conversations	·.1 .1	1 1		2.1		
10.	Discussing FAQ's in interviews v			•	2 hours		
	better insight in to interviews / Ac	virvities inrough v	TI Comm	unity Kadio			
	l		Total I	Practical Hours	30 hours		
Mod	le of evaluation: Online Quizzes, P	resentation, Role	play, Grou	p Discussions, A			
	i Project						
	ommended by Board of Studies	22-07-2017					
App	roved by Academic Council	No. 46	Date	24-8-2017			

Course Code	Course Title	L T P J C
ENG5002	Professional and Communication Skills	0 0 2 0 1
Pre-requisite	ENG5001	Syllabus
		version
		1.1
Course Objecti		
	dents to develop effective Language and Communication Skills	
	students' Personal and Professional skills	
3. To equip the s	students to create an active digital footprint	
Expected Cours	se Outcome:	
	er-personal communication skills	
	blem solving and negotiation skills	
1 1	yles and mechanics of writing research reports	
	tter public speaking and presentation skills	
	equired skills and excel in a professional environment	
Module:1 P	ersonal Interaction	2hours
Introducing One	eself- one's career goals	
A ativitan OWOT	Analysis	
Activity: SWOT	Analysis	
Module:2 In	nterpersonal Interaction	2 hours
	ommunication with the team leader and colleagues at the workplace	2 110015
interpersonal Ce	simulated for with the team leader and concagues at the workplace	
Activity: Role P	lays/Mime/Skit	
	ocial Interaction	2 hours
	edia, Social Networking, gender challenges	
Activity: Creatin	ng LinkedIn profile, blogs	
	· · · · · · · · · · · · · · · · · · ·	4 1
Module:4 R	Résumé Writing	4 hours
Identifying job r	requirement and key skills	
Activity: Prepar	e an Electronic Résumé	
Module:5 In	nterview Skills	4 hours
Placement/Job I	nterview, Group Discussions	I
	Interview and mock group discussion	
y		
Module:6 R	Report Writing	4 hours
Language and N	Iechanics of Writing	
Activity: Writin	g a Report	
Module:7 S	tudy Skills: Note making	2hours
Summarizing the	e report	
-	ct, Executive Summary, Synopsis	

Module:8 Interpreting skills			
-	in tables and graphs		
Activity: Tra	nscoding		
Module:9	Presentation Skills	4 hours	
Oral Presenta	ation using Digital Tools		
	I presentation on the given topic using appropriate non-verbal cues		
110011091 010			
Module:10	Problem Solving Skills	4 hours	
Problem Solv	ving & Conflict Resolution		
Activity: Cas	e Analysis of a Challenging Scenario		
2	Total Lecture hours	: 30hours	
Tort Drah			
Text Book(s Bhatna) gar Nitin and Mamta Bhatnagar, Communicative English For		
Engine	ers And Professionals, 2010, Dorling Kindersley (India) Pvt. Ltd.		
Reference B		<u> </u>	
	kman and Christopher Turk, Effective Writing: Improving Scientific, ss Communication, 2015, Routledge	Technical and	
	Bairaktarova and Michele Eodice, Creative Ways of Knowing in En er International Publishing	gineering, 2017,	
	d A Whitcomb & Leslie E Whitcomb, Effective Interperso unication Skills for Engineers, 2013, John Wiley & Sons, Inc., Hobok		
	atil, Henk Eijkman & Ena Bhattacharya, New Media Communic ers and IT Professionals, 2012, IGI Global, Hershey PA.	ation Skills for	
Mode of Eva	luation: CAT / Assignment / Quiz / FAT / Project / Seminar		
	lenging Experiments (Indicative)		
1. SWOT weakne	Analysis – Focus specially on describing two strengths and two esses	2 hours	
2. Role Pl	ays/Mime/Skit Workplace Situations	4 hours	
	Social Media – Create a LinkedIn Profile and also write a page or areas of interest	2 hours	
4. Prepare	e an Electronic Résumé and upload the same in vimeo	2 hours	
-	discussion on latest topics	4 hours	
	Writing – Real-time reports	2 hours	
7 Writing articles	g an Abstract, Executive Summary on short scientific or research	4 hours	
	oding – Interpret the given graph, chart or diagram	2 hours	

9 Oral presentation on the given topic using appropriate non-verbal cues					4 hours		
10	Problem Solving Case Analysi		4 hours				
	Total Laboratory Hours 30 hours						
Mod	le of evaluation: : Online Quizzes,	Presentation, Role	e play, Gro	oup Discussions,	Assignments,		
Mini	i Project						
Reco	ommended by Board of Studies	22-07-2017					
App	roved by Academic Council	No. 47	Date	05-10-2017			

Course Code	Course Title	L T P J C
GER5001	Deutsch für Anfänger	2 0 0 0 2
Pre-requisite	NIL	Syllabus
_		version
		v.1
Course Objectives		
	udents the necessary background to:	
	ents to read and communicate in German in their day to day life	
2. become ind	• •	
3. make them	understand the usage of grammar in the German Language.	
Expected Course		
The students will b		
	of German language in their day to day life.	
	onjugation of different forms of regular/irregular verbs.	
	le to identify the gender of the Nouns and apply articles appropri	lately.
	n language skill in writing corresponding letters, E-Mails etc.	To from
	of translating passages from English-German and vice versa and	To frame
simple dialogues b	ased on given situations.	
Module:1		3 hours
	ann actainnea. Landachunda, Alinhahat, Danaanalanaa anna Mar	
0 0	sungsformen, Landeskunde, Alphabet, Personalpronomen, Ver	b Konjugation,
	-fragen, Aussagesätze, Nomen – Singular und Plural	
Lernziel:		
Elementares Verst	ändnis von Deutsch, Genus- Artikelwörter	
Module:2		3 hours
	erben (regelmässig /unregelmässig) die Monate, die Wochentage	
5 0	n, Artikel, Zahlen (Hundert bis eine Million), Ja-/Nein- Frage, Ir	
Sie	n, Antikel, Zamen (Hundert bis ente Winnon), su Attem Prage, fr	iiperativ iint
Lernziel :		
	er Hobbys erzählen, über Berufe sprechen usw.	
,		
Module:3		4 hours
Possessivpronome	n, Negation, Kasus- AkkusatitvundDativ (bestimmter, unbest	
-	Modalverben, Adjektive, Uhrzeit, Präpositionen, Mahlzeiten	
Getränke		, , ,
Lernziel :		
	rben, Verwendung von Artikel, über Länder und Sprachen spre	chen jiher eine
Wohnung beschrei	• • •	enen, uber ente
Module:4		6 hours
	Deutsch – Englisch / Englisch – Deutsch)	0 Hourb
Lernziel :	Seatson Englison Englison Deutson)	
Grammatik – Wort	schatz — Übung	
	senarz – obung	
Module:5		5 hours
	indmap machen,Korrespondenz- Briefe, Postkarten, E-Mail	5 110018
	memap machen, Konespondenz- Dhere, Fostkatten, E-Mall	

Leri	nziel :				
-	tschatzbildung und aktiver Spra	ch gebrauch			
		8			
Mod	lule:6				3 hours
Aufs	sätze :				
Mein	ne Universität, Das Essen, mein	Freund oder meine H	Freundin, n	neine Familie, eir	Fest in
Deut	tschland usw				
Mod	lule:7				4 hours
Dial	oge:				
а	a) Gespräche mit Familienmitg	liedern, Am Bahnhot	f,		
ł	b) Gespräche beim Einkaufen ;	in einem Supermark	t; in einer	Buchhandlung;	
C	c) in einem Hotel - an der Reze	ption ;ein Termin be	eim Arzt.		
Tref	fen im Cafe				
	lule:8				2 hours
	st Lectures/Native Speakers / H	Feinheiten der deuts	chen Sprac	che, Basisinform	ation über die
deut	schsprachigen Länder				
			Total	Lecture hours:	30 hours
	t Book(s)				
	Studio d A1 Deutsch als Fi	remdsprache, Herr	nann Fun	k, Christina K	uhn, Silke
	Demme : 2012				
	erence Books		1 5	1.0.1.11.1.0	
	Netzwerk Deutsch als Fremdspi Sieber, 2013	rache A1, Stefanie D	engler, Pau	il Rusch, Helen S	Schmtiz, Tanja
2	Lagune ,Hartmut Aufderstrasse	e, Jutta Müller, Thom	nas Storz, 2	2012.	
	Deutsche SprachlehrefürAUslän				
	ThemenAktuell 1, HartmurtAuf	derstrasse, Heiko Bo	ock, Mecht	hildGerdes, Jutta	Müller und
	Helmut Müller, 2010				
	www.goethe.de				
	wirtschaftsdeutsch.de				
	hueber.de				
	klett-sprachen.de				
	www.deutschtraning.org				
	e of Evaluation: CAT / Assignn	-	:/FAT		
	ommended by Board of Studies	04-03-2016	T		
App	roved by Academic Council	41	Date	17-06-2016	

C	1	0		
Course co FRE500		Course Title FRANCAIS FONCTIONNEL		L T P J C 2 0 0 0 2
Pre-requisit		FRANCAIS FONCTIONNEL Nil		2 0 0 0 2 Syllabus
r re-requisit	e			version
				1.0
Course Obj	ectives			1.0
v		idents the necessary background to:		
know sport	/ledge s/hobb	competence in reading, writing, and speaking of vocabulary (related to profession, emoti es, classroom and family). Ficiency in French culture oriented view point.		
Expected Co	ourse (Jutcome		
The students				
		ne daily life communicative situations via personal pro	onouns, en	nphatic
		lutations, negations, interrogations etc.	,	1
2. create	e comn	nunicative skill effectively in French language via reg	ular / irreg	ular verbs.
3. demo	onstrate	comprehension of the spoken / written language in tr	anslating s	simple
sente				
		and demonstrate the comprehension of some particula	r new rang	ge of unseen
	en mate			
5. demo	onstrate	a clear understanding of the French culture through t	he languag	ge studied.
	0.1			21
		, Se présenter, Etablir des contacts	de l'anné	3 hours
		s nombres (1-100), Les jours de la semaine, Les mois ls Toniques, La conjugaison des verbes réguliers, L		
-		etre / aller / venir / faire etc.	a conjuga	ison des verbes
integuners- a		tre / aner / venni / nane etc.		
Module:2	Prései	iter quelqu'un, Chercher un(e) correspon	dant(e).	3 hours
		nder des nouvelles d'une personne.	uunt(0),	c nours
La co	onjugai	son des verbes Pronominaux,	La	Négation,
L'interrogati	ion ave	c 'Est-ce que ou sans Est-ce que'.		
-		^ ^ ^		
Module:3	Situer	un objet ou un lieu, Poser des questions		4 hours
		défini), Les prépositions (à/en/au/aux/sur/dans/avec	etc.), L'an	
Les heures	en fra	nçais, La Nationalité du Pays, L'adjectif (La Cou	leur, l'adj	ectif possessif,
l'adjectif dé	monstr	atif/ l'adjectif interrogatif (quel/quelles/quel	le/quelles)	, L'accord des
adjectifs ave	c le no	m, L'interrogation avec Comment/ Combien / Où etc.	,	
		des achats, Comprendre un texte court, Dema er le chemin.	nder et	6 hours
	_	e :(français-anglais / anglais –français)	I	
	r	<u> </u>		
Module:5	Trouv	er les questions, Répondre aux questions générales	s en	5 hours
	frança			
	<u> </u>	Mettez les phrases aux pluriels, Faites une phrase	e avec les	mots donnés,
		es données au Masculin ou Féminin, Associez les phra		
-	-			

ule:6	Comment ecrire un passa	age			3 hours			
ivez :								
amille /	La Maison, /L'université /L	Les Loisirs/ La Vie	e quotidien	ne etc.				
0								
/								
,	1							
) Enti	re le client et le médecin							
ule:8	Invited Talk: Native spe	eakers			2 hours			
			Total Lo	ecture hours:	30 hours			
	·	,			,			
		urdet, J. Pécheur, I	Publisher C	CLE Internation	al, Paris 2010.			
			• • •	.				
	EXIONS 1, Méthode de fra	nçais, Régine Méi	rieux, Yves	s Loiseau,Les E	Editions Didier,			
2004.								
GONDI		·		.	<u> </u>			
	-	ercices, Régine M	érieux, Yv	es Loiseau, Les	s Editions			
Didier,	2004.							
					• • • •			
		, · ·		0	ique M.			
Kiziriai	n, Béatrix Sampsonis, Moni	que Waendendrie	s, Hachett	e livre 2006.				
6 5								
0 \								
oved b	y Academic Council	INO.41	Date	17-06-2016				
	ivez : amille / ule:7) Rése) Entro) Entro) Entro) Entro) Entro) Entro) Entro) Entro () Parn) Entro () Entro	ivez : amille /La Maison, /L'université /I ule:7 Comment ecrire un dialo ogue:) Réserver un billet de train) Entre deux amis qui se rencontr Parmi les membres de la famille) Entre le client et le médecin ule:8 Invited Talk: Native spe Book(s) Echo-1, Méthode de français, J. Gi Echo-1, Cahier d'exercices, J. Gira rence Books CONNEXIONS 1, Méthode de français 2004. CONNEXIONS 1, Le cahier d'exercices, Didier, 2004. ALTER EGO 1, Méthode de français, Moni-	ivez : amille /La Maison, /L'université /Les Loisirs/ La Vie ule:7 Comment ecrire un dialogue ogue:) Réserver un billet de train) Entre deux amis qui se rencontrent au café Parmi les membres de la famille) Entre le client et le médecin ule:8 Invited Talk: Native speakers Book(s) Echo-1, Méthode de français, J. Girardet, J. Pécheur, I rence Books CONNEXIONS 1, Méthode de français, Régine Mét 2004. CONNEXIONS 1, Le cahier d'exercices, Régine Mét 2004. CONNEXIONS 1, Le cahier d'exercices, Régine Mét 2004. ALTER EGO 1, Méthode de français, Annie Berthe Kizirian, Béatrix Sampsonis, Monique Waendendrie e of Evaluation: CAT / Assignment / Quiz / Seminar mmended by Board of Studies 26.02.2016	ivez : amille /La Maison, /L'université /Les Loisirs/ La Vie quotidien ule:7 Comment ecrire un dialogue ogue:) Réserver un billet de train) Entre deux amis qui se rencontrent au café) Parmi les membres de la famille) Entre le client et le médecin ule:8 Invited Talk: Native speakers Total La Book(s) Echo-1, Méthode de français, J. Girardet, J. Pécheur, Publisher Echo-1, Cahier d'exercices, J. Girardet, J. Pécheur, Publisher C rence Books CONNEXIONS 1, Méthode de français, Régine Mérieux, Yves 2004. CONNEXIONS 1, Le cahier d'exercices, Régine Mérieux, Yv Didier, 2004. ALTER EGO 1, Méthode de français, Annie Berthet, Catherin Kizirian, Béatrix Sampsonis, Monique Waendendries , Hachett e of Evaluation: CAT / Assignment / Quiz / Seminar / FAT mmended by Board of Studies 26.02.2016	ivez : amille /La Maison, /L'université /Les Loisirs/ La Vie quotidienne etc. ule:7 Comment ecrire un dialogue ogue:) Réserver un billet de train) Entre deux amis qui se rencontrent au café Parmi les membres de la famille) Entre le client et le médecin ule:8 Invited Talk: Native speakers Total Lecture hours: Book(s) Echo-1, Méthode de français, J. Girardet, J. Pécheur, Publisher CLE Internation Echo-1, Méthode de français, J. Girardet, J. Pécheur, Publisher CLE Internation rence Books CONNEXIONS 1, Méthode de français, Régine Mérieux, Yves Loiseau, Les É 2004. CONNEXIONS 1, Le cahier d'exercices, Régine Mérieux, Yves Loiseau, Les É 2004. ALTER EGO 1, Méthode de français, Annie Berthet, Catherine Hugo, Véron Kizirian, Béatrix Sampsonis, Monique Waendendries , Hachette livre 2006. e of Evaluation: CAT / Assignment / Quiz / Seminar / FAT mmended by Board of Studies 26.02.2016			

Course code		Course Title			L	T	P	J	C
SET 5001	SCIENCE, EN	GINEERING AN	D TECHN	OLOGY	0	0	0		2
		PROJECT-	[
Pre-requisite					Syllab	ous	Ve	rsio	on
Anti-requisite								-	1.10
Course Objectives	:								
 To inculcate 	opportunity to involve research culture the rational and innov			e / enginee	ring				
Expected Course (On completion of th	Dutcome: his course, the student	should be able to							
On completion of th	iis course, the student		•						
• 1	blems that have releva		ndustrial ne	eeds					
	pendent thinking and								
3. Demonstrate	e the application of re	levant science / er	igineering j	principles					
Modalities / Requi	rements								
-	r group projects can b	e taken up							
	terature survey in the	-							
	/Engineering principl		ied issues						
4. Adopt releva	ant and well-defined /	innovative metho	dologies to	o fulfill the	specifi	ed o	bje	cti	ve
-	of scientific report in		-		-		2		
Student Assessmer	nt : Periodical review	s, oral/poster pres	entation						
Recommended by E	Board of Studies	17-08-2017							
Approved by Acade	emic Council	No. 47	Date	05-10-201	.7				

Course code	Course code Course Title					L	Τ	P	J	С
SET 5002	SCIENCE, EN	GINEERING AN PROJECT- I		NOLOGY		0	0	0	0	2
Pre-requisite					Syll	abı	ıs V	Ve	rsic	n
Anti-requisite]	1.10
Course Objectives	•									
	ide opportunity to inv		elated to so	cience / engi	neeri	ng				
2. To incul	cate research culture									
3. To enha	nce the rational and in	nnovative thinking	g capabiliti	ies						
Expected Course (Outcome:									
On completion of the	his course, the studen	t should be able to	:							
1. Identify pro	oblems that have rele	vance to societal /	industrial	needs						
• 1	lependent thinking an									
	te the application of r	-	ngineering	g principles						
Modalities / Requi	**		0 0							
	al or group projects c	can be taken up								
	in literature survey in									
	ence/Engineering prir		entified iss	ues						
	relevant and well-de				fulfil	l tl	he	sp	eci	fied
objective										
5. Submiss	5. Submission of scientific report in a specified format (after plagiarism check)									
	nt : Periodical review									
Recommended by Board of Studies 17-08-2017										
Approved by Academic Council No. 47 Date 05-10-2017										

Course cod	Course code Course title					
STS 5001		Essentials of Business Etiquette and problem solving	3 0 0 0 1			
Pre-requisi	ite	None	Syllabus version			
Course Ob	iectives	•				
		the students' logical thinking skills				
		strategies of solving quantitative ability problems				
		e verbal ability of the students				
4. To e	enhance	critical thinking and innovative skills				
E	N. A					
Expected C						
	-	idents to use relevant aptitude and appropriate language to expressive the message to the target audience clearly	s themselves			
		s will be able to be proficient in solving quantitative aptitude and	verbal ability			
		various examinations effortlessly	verbar ability			
-	1					
Module:1		ess Etiquette: Social and Cultural Etiquette and Writing	9 hours			
	Comp	any Blogs and Internal Communications and Planning and				
	Writin	ng press release and meeting notes				
	~	ustoms, Language, Tradition, Building a blog, Developing brand				
Understandi plan, Progre	ing the a	Competition, Open and objective Communication, Two way dialo audience, Identifying, Gathering Information, Analysis, Determin k, Types of planning, Write a short, catchy headline, Get to the P bject in the first paragraph., Body – Make it relevant to your audi	ing, selecting oint –			
Module:2	Study	skills – Time management skills	3 hours			
Prioritizatio adhering to		rastination, Scheduling, Multitasking, Monitoring, working unde	r pressure and			
Module:3	Prese	ntation skills – Preparing presentation and Organizing	7 hours			
Mouule.5	mater	ials and Maintaining and preparing visual aids and Dealing uestions	7 110013			
sky thinkin presentation posters, Set	ng, Intr 1, Impor tting ou	PowerPoint presentation, Outlining the content, Passing the Eleve oduction, body and conclusion, Use of Font, Use of Co tance and types of visual aids, Animation to captivate your audie at the ground rules, Dealing with interruptions, Staying in o g difficult questions	olor, Strategic nce, Design of			
Module:4	Ouan	titative Ability -L1 – Number properties and Averages and	11 hours			
	-	essions and Percentages and Ratios				
Averages,	Weight	s, Factorials, Remainder Theorem, Unit digit position, Tens ed Average, Arithmetic Progression, Geometric Progressions se & Decrease or successive increase, Types of ratios and propor	on, Harmonic			

Mo	Iodule:5 Reasoning Ability-L1 – Analytical Reasoning		8 hours
		gement (Linear and circular & Cross Variable Relationship), Blood Relationship, Blood Relationship/grouping, Puzzle test, Selection Decision table	ons,
Mo	dule:6	Verbal Ability-L1 – Vocabulary Building	7 hours
•	•	& Antonyms, One-word substitutes, Word Pairs, Spellings, Idioms, Sente h, Analogies	nce
		Total Lecture hours:	45 hours
Ref	erence 1	Books	
1.	Tools f	Patterson, Joseph Grenny, Ron McMillan, Al Switzler (2001) Crucial Conv For Talking When Stakes are High. Bangalore. McGraw-Hill Contemporary	y
2.	Dale C Books	Carnegie, (1936) How to Win Friends and Influence People. New York	k. Gallery
3.	Scott P	eck. M (1978) Road Less Travelled. New York City. M. Scott Peck.	
4.	FACE	(2016) Aptipedia Aptitude Encyclopedia. Delhi. Wiley publications	
5.	ETHN	US (2013) Aptimithra. Bangalore. McGraw-Hill Education Pvt. Ltd.	
We	bsites:		
1.	<u>www.c</u>	halkstreet.com	
2.	www.s	killsyouneed.com	
3.	www.n	nindtools.com	
4.	www.t	hebalance.com	
5.	www.e	2 <u>uru.000</u>	
		valuation: FAT, Assignments, Projects, Case studies, Role plays, nts with Term End FAT (Computer Based Test)	

Course code	Course title	L T P J C						
STS 5002	Preparing for Industry	3 0 0 0 1						
Pre-requisite	None	Syllabus						
		version						
		1						
Course	1. To challenge students to explore their problem-solving skills							
Objectives:								
ability questions 3. To have working knowledge of communicating in English								
	3. To have working knowledge of communicating in Eng	lish						
Expected Course	1. Enabling students to simplify, evaluate, analyze and us	e functions and						
Outcome:								
outcome.	 The students will be able to interact confidently and use de 	•						
	models effectively	0						
	3. The students will be able to be proficient in solving qua	antitative						
	aptitude and verbal ability questions of various examin	ations						
	effortlessly							
Module:1	Interview shills Turnes of interview and Techniques to	2 h a						
Mouule:1	Interview skills – Types of interview and Techniques to face remote interviews and Mock Interview	3 hours						
	lace remote interviews and wock interview							
Structured and unst	ructured interview orientation, Closed questions and hypothetica	al questions,						
	ective, Questions to ask/not ask during an interview, Video inter							
Recorded feedback,	Phone interview preparation, Tips to customize preparation for	personal						
interview, Practice	rounds							
Module:2	Resume skills – Resume Template and Use of power	2 hours						
	verbs and Types of resume and Customizing resume							
Structure of a stand	lard resume, Content, color, font, Introduction to Power verbs	and Write up,						
	resume, Frequent mistakes in customizing resume, Layout -							
different company's	requirement, Digitizing career portfolio							
Module:3	Emotional Intelligence - L1 – Transactional Analysis and	12 hours						
wiodule.5	Brain storming and Psychometric Analysis and Rebus	12 110015						
	Puzzles/Problem Solving							
	r uzzies/ r robielli Solvilig							
Introduction, Cont	tracting, ego states, Life positions, Individual Brainsto	orming, Group						
Brainstorming, Step	pladder Technique, Brain writing, Crawford's Slip writing app	roach, Reverse						
-	r bursting, Charlette procedure, Round robin brainstormir	ng, Skill Test,						
Personality Test, M	ore than one answer, Unique ways							
Module:4	Quantitative Ability I.3 Domistation Combinations	14 hours						
wiouule:4	Quantitative Ability-L3 – Permutation-Combinations	14 Hours						
	and Probability and Geometry and mensuration and							
	Trigonometry and Logarithms and Functions and							
	Quadratic Equations and Set Theory							
Counting Groupin	g, Linear Arrangement, Circular Arrangements, Condition	al Probability						
U 1	ependent Events, Properties of Polygon, 2D & 3D Figures, Ar	•						
independent and D	ependent Lyonto, Properties of Polygon, 2D & 5D Figures, Al	cu cu volumos,						

0	ces, Simple trigonometric functions, Introduction to logarithms, luction to functions, Basic rules of functions, Understand				
0	robabilities of Quadratic Equations, Basic concepts of Venn D	v ~			
Equations, rates a					
Module:5	Reasoning ability-L3 – Logical reasoning and Data7 houAnalysis and Interpretation7				
	logic, Sequential output tracing, Crypto arithmetic, Data Sufficie anced, Interpretation tables, pie charts & bar chats	ency, Data			
Module:6	Verbal Ability-L3 – Comprehension and Logic	7 hours			
0 1	nsion, Para Jumbles, Critical Reasoning (a) Premise and Conclus erence, (c) Strengthening & Weakening an Argument	ion, (b)			
	Total Lecture hours:	45 hours			
References	 Michael Farra and JIST Editors(2011) Quick Resume & Book: Write and Use an Effective Resume in Just One I Paul, Minnesota. Jist Works Daniel Flage Ph.D(2003) The Art of Questioning: An In Critical Thinking. London. Pearson FACE(2016) Aptipedia Aptitude Encyclopedia.Delhi. V publications 	Day. Saint ntroduction to			
Mode of Evaluation	on: FAT, Assignments, Projects, Case studies, Role plays,				
	h Term End FAT (Computer Based Test)				

Course Code	Course Title		Т	Р	J	С
ECE6099	9 Masters Thesis			0	0	16
Pre-requisite	As per the academic regulations	Syllabus version		sion		
		1.0				

Course Objectives:

To provide sufficient hands-on learning experience related to the design, development and analysis of suitable product / process so as to enhance the technical skill sets in the chosen field.

Expected Course Outcome:

At the end of the course the student will be able to

- 1. Formulate specific problem statements for ill-defined real life problems with reasonable assumptions and constraints.
- 2. Perform literature search and / or patent search in the area of interest.
- 3. Conduct experiments / Design and Analysis / solution iterations and document the results.
- 4. Perform error analysis / benchmarking / costing
- 5. Synthesise the results and arrive at scientific conclusions / products / solution
- 6. Document the results in the form of technical report / presentation

Contents

Capstone Project may be a theoretical analysis, modeling & simulation, experimentation & analysis, prototype design, fabrication of new equipment, correlation and analysis of data, software development, applied research and any other related activities.

Project should be for two semesters based on the completion of required number of credits as per the academic regulations.

Should be individual project.

In case of group projects, the individual project report of each student should specify the individual's contribution to the group project.

Carried out inside or outside the university, in any relevant industry or research institution.

Publications in the peer reviewed journals / International Conferences will be an added advantage

Mode of Evaluation: Periodic reviews, Presentation, Final oral viva, Poster submission							
Recommended by Board of	10-06-2015						
Studies							
Approved by Academic Council	No. 37	Date	16-06-2015				

Course Code	Course Title	L	Т	Р	J	С
ECE5014	ASIC DESIGN	3	0	2	0	4
Pre-requisite	Nil					

Course Objective :

The course is aimed to

- 1. explain the types of ASIC and typical ASIC design Flow.
- 2. give the students an understanding of HDL coding guidelines and synthesizable HDL constructs.
- 3. explain the RTL synthesis Flow with respect to different cost function.
- 4. teach the various timing parameter and how to perform Static Timing Analysis for ASIC chips.
- 5. discuss the various abstraction levels in physical design and guidelines at each abstraction level.
- 6. provide detailed insight on importance of physical design verification

Expected Course Outcome :

At the end of the course the student will be able to

- 1. Understand different types of ASICs and design flows.
- 2. Design digital systems by adhering to synthesizable HDL constructs.
- 3. Synthesize the given design by considering various constraints and to optimize the same.
- 4. Understand various timing parameters and compute computation time for a given design using static timing analysis.
- 5. Perform physical design by adhering to guidelines.
- 6. Apprehend the importance of physical design verification.
- 7. Design ASIC based systems using industry standard tools.

Module:1 ASIC Design Methodology & Design Flow

Implementation Strategies for Digital ICs: Custom IC Design- Cell-based Design Methodology -Array based implementation approaches - Traditional and Physical Compiler based ASIC Flow.

Module:2 Verilog HDL Coding Style for Synthesis

HDL Coding style - Guidelines and Recommendation - FSM Coding Guideline and Coding Style for Synthesis.

Module:3 **RTL Synthesis**

RTL synthesis Flow - Synthesis Design Environment & Constraints - Architecture of Logic Synthesizer - Technology Library Basics- Components of Technology Library -Synthesis Optimization- Technology independent and Technology dependent synthesis- Data path Synthesis -Low Power Synthesis - Timing driven synthesis- Formal Verification.

Module:4 **Timing Parameters**

Timing Parameter Definition – Setup Timing Check- Hold Timing Check- Multicycle Paths- False Paths - Clocking of Synchronous Circuits.

Module:5 **Static Timing Analysis**

Timing Analysis - Clock skew optimization - Clock Tree Synthesis.

Module:6 **Physical Design**

Detailed step in Physical Design Flow- Guidelines for Floor plan, Placement and routing. Conducting layers and their characteristics - Cell-based back-end design -ECO - Packaging-Layout Issues-Preventing electrical overstress.

6 hours

8 hours

5 hours

7 hours

8 hours

4 hours

Modu	ıle:7	Physical Design Verification		5 hours
		tion techniques-Post-layout design verificatio	n.	
Modu	ıle:8	Contemporary issues:		2 hours
				_ 100010
		Total Lecture hours:		45 hours
Text]	Book(s)			
1.		nshuBhatnagar, Advanced ASIC Chip Synthe	sis, Kluwer Academic Publisher	, Second
		n, 2012.		, ,
Refer	ence Bo	oks		
1.	1	Brunvand, Digital VLSI Chip Design with Ca	dence and Synopsys CAD Tools	s, Addison
		y, First Edition, 2010.	5 1 5	,
2.		sker and RakeshChadha, Static Timing Anal	ysis for Nanometer Designs, Sp	ringer US,
		Edition, 2010.		0,
Mode	of Eva	luation:Continuous Assessment Test -I (C	AT-I), Continuous Assessmen	t Test –II
		ninar / Challenging Assignments / Completion		
		ndustrial problems, Final Assessment Test (F		U
		enging Experiments (Indicative)	· · · · · · · · · · · · · · · · · · ·	
1.	-	- I Design of digital architecture		12 hours
		n Specification: Starting with the soda mach	ine dispenser design described	
	0	ure, create a block diagram and high-level st	1 0	
		iser that has a choice of two soda types, and the		
	-	mer. A coin detector provides the circuit with		
		e clock cycle when a coin is detected, and		
		value in cents. Two 8-bit input s1 and s2 in		
		es. The user's soda selection is controlled b		
		pushed will output 1 for one clock cycle. I	•	
		e for their selection, the circuit should set eit		
		lock cycle, causing the selected soda to be		
		t should also set an output bit cr to 1 for		
		ed, and should output the amount of chan	, ,	
	-	t ca. Use the RTL design method to convert the		
	-	oller and a data path. Design the data pat	-	
		oller to the point of an FSM only.		
2.		-II Logical Synthesis of digital architectur	e	6 hours
		design and timing constraints :		
	11.0	g constraints: set_clock ,set_clock_uncertain	ty, set clock latency,	
		ock_transition, set_input_delay, set_output_d		
		ulticycle_path.		
		constraints are: set_max_fanout, set_max_tra	nsition and	
		ax_capacitance.		
		ization constraints :set_max_area, set_min_a	rea,	
		ax_leakegeandset_max_dynamic.	<i>,</i>	
		-III Netlist Optimization and Formal Ver	ification	4 hours
3	Phase			
3.				
3.	Apply	power optimization constraints, Gate Level		
3.	Apply verific		Simulation and Formal	4 hours

5. Phase - VPhysical Verification of digital architecture							
	set_fix_multiple_port_nets, write_physical_constraints and write_parasitics						
	Total Laboratory hours: 30 hours						
Mode	Mode of Evaluation: Continuous assessment of challenging experiments /Final Assessment Test						
(FAT).							
Recom	Recommended by Board of Studies 13-12-2015						
Approv	Approved by Academic CouncilNo. 4018-03-2016						

Course Code	Course Title	L T P J C
ECE5015	DIGITAL IC DESIGN	3 0 0 4 4
Pre-requisite	Nil	
Course Object	ive :	
The course is ai	med to	

- 1. apply the models for state-of-the-art VLSI components, fabrication steps, hierarchical design flow and semiconductor business economics to judge the manufacturability of a design and assess its manufacturing costs.
- 2. focus on the systematic analysis and design of basic digital integrated circuits in CMOS technology.
- 3. enhance problem solving and creative circuit design techniques.
- 4. emphasize on the layout design of various digital integrated circuits.
- 5. focus on the methodologies and design techniques related to digital integrated circuits.

Expected Course Outcome :

At the end of the course the student will be able to

- 1. Understand design metric and MOS physics
- 2. Design layout for various digital integrated circuits.
- 3. Design the CMOS inverter with optimized power, area and timing.
- 4. Design static and dynamic digital CMOS circuits.
- 5. Understand the timing concepts in latch and flip-flops.
- 6. Design CMOS memory arrays.
- 7. Understand interconnect and clocking issues.

Module:1 Introduction:

Issues in Digital IC Design- Quality Metrics of a Digital Design - MOS Transistor Theory.

Module:2 Fabrication Technologies:

VLSI Manufacturing Process Steps - Crystal Growth - Wafer cleaning – Oxidation - Thermal Diffusion - Ion Implantation – Lithography –Epitaxy – Metallization -Dry and Wet etching and Packaging.

Fabrication of MOSFET with Metal Gate and Self-aligned Poly-Gate Processes with details on CMOS Design Rules and Layouts, Fabrication of CMOS inverter with details on Design Rules and Layouts.

Module:3 The CMOS Inverter:

5 hours

8 hours

3 hours

7 hours

Static CMOS Inverter- Static and Dynamic Behavioural Practices of CMOS Inverter – Noise Margin.

Components of Energy and Power – Switching -Short-Circuit and Leakage Components. Technology scaling and its impact on the inverter metrics - Passive and Active Devices.

Module:4 Static & Dynamic CMOS Design:

Complementary CMOS -Ratioed Logic (Pseudo NMOS, DCVSL) - Pass Transistor Logic -Transmission gate logic - Dynamic Logic Design Considerations - Speed and Power Dissipation of Dynamic logic -Signal integrity issues -Domino Logic.

Module:5	Module:5 CMOS Sequential Logic Circuit Design:	
Introductio	n - Static Latches and Registers - Dynamic Latches and Registers -	- Pulse Based

Мо	dule:6	Designing Memory & Ar	rav structures.		7 hours
			mory peripheral circuitry - M	emory reliabilit	
		pation in memories.	mory peripheral cheditry in	emory rendom	y and yield
Mo	dule:7	Interconnects and Timing	g Issues:		8 hours
Res	sistive, C		arasitics - Computation of R	, L and C for	given inter-
con	nects - E	Buffer Chains - Timing class	ification of digital systems - S	ynchronous Des	sign - Origins
		*	rformance - Clock Distribution	-	
	-	-	s -Clock Synthesis and Sync	chronization us	ing a Phase-
Loc	ked Loo	p.			
24	110	Contonno ano muliague ogu			
Mo	dule:8	Contemporary issues:			2 hours
			Τ _α <i>t</i> _α 1Τ.	ecture hours:	45 hours
		<u></u>	1 otal Lo	ecture nours:	45 nours
	t Book(,			•••
1.		Perspective, PHI, Second E	asan, BorivojeNikolic, Digita	al Integrated C	ircuits: A
2.	0	1	Ayan Banerjee, CMOS VLS	I Design: A C	ircuit and
2.		s Perspective, Pearson Educ	•	i Desigii. A C	neun and
Ref	erence l				
1.			, CMOS Digital Integrated	Circuits - Ana	alysis and
	Design	, McGraw-Hill, Fourth Editi	on, 2014.		
2.			Principles: Si and GaAs, John	n Wiley and Sor	ns, Second
	Edition	·			
			sment Test –I (CAT-I), Cont		
			nments / Completion of MOO	C / Innovative	ideas leading
		for industrial problems, Fina	al Assessment Test (FAT).		
LIS	U	ects (Indicative)	nparator by using 8T full adde	re	
		0	design using low power full a		
		6	ver efficient flip-flop using trai	U	
			1 1 0	0	lers.
	 Design of high performance 5:32 decoder using 2:4,3:8 mixed logic line decoders. Design of current comparator using FINFET 				
	6. Analysis of leakage current and leakage power reduction during reduction in CMOS				
		M cell			
		gn of encoder for a 5GS/S :			
	8. Desi	gn a 65 nm reliable 6T CM	OS SRAM cell with minimum	n size transistors	
Mo	de of Ev	aluation:Review I, II and III			
Rec	commend	led by Board of Studies	13-12-2015		
		y Academic Council	No. 40	18-03-2016	

Registers - Sense Amplifier based registers -Latch vs. Register based pipeline structures.

33

Course Code	Course Title	L	T	P	J	С
ECE5016	ANALOG IC DESIGN	3	0	2	0	4
Pre-requisite	Nil					

Course Objectives :

The course is aimed to

- 1. analyze and design single-ended and differential IC amplifiers.
- 2. understand the relationships between devices, circuits and systems.
- 3. emphasize the design of practical amplifiers, small systems and their design parameter trade-offs.

Expected Course Outcome :

At the end of the course the student will be able to

- 1. Analyse low-frequency characteristics of single-stage amplifiers and differential amplifiers.
- 2. Analyse high-frequency response and noise of amplifiers.
- 3. Understand the feedback concepts.
- 4. Analyse and Design of High Gain Amplifiers.
- 5. Understand stability analysis and frequency compensation techniques of amplifiers.
- 6. Understand the basic concepts, non-idealities and applications of PLLs.
- 7. Design and characterize amplifiers according to design specifications in Cadence CAD software.

Module:1 Current source and Amplifier design:

MOS Device models, MOS Current Sources and Sinks, Current Mirror: Basic Current Mirrors, Cascode current Mirrors. Bandgap references. Single stage Amplifies: Basic concepts, Common Source stage, Common Gate stage, Cascode stage. Differential stage: Single ended and Differential operation. Basic Differential Pair.

Module:2	Frequency response and Noise analysis of Amplifiers:	8 hours
Millen offer	the Endeway and a stand of Common Sources stores. Common Cate stores	Casaada stass

Miller effect, Frequency response of Common Source stage, Common Gate stage, Cascode stage and Differential pair. Noise in Amplifiers: Common Source stage, Common Gate stage, Cascode stage, Differential pair. Noise Bandwidth.

Module:3 | Feedback Amplifiers:

Ideal feedback equation, Gain sensitivity, Effect of Negative Feedback on Distortion, Types of Feedback Amplifiers. Feedback configurations: voltage-voltage, current-voltage, current-current, voltage-current feedback. Practical configurations and Effect of loading.

Module:4 Operational Amplifier

Common mode Feedback circuits, Op Amp CMRR requirements, Need for Single and Multistage amplifiers, Effect of loading in Differential stage. Performance Analysis: DC gain, Frequency response, Noise, Mismatch, Slew rate of cascode and two stage Op Amps, Fully Differential Op Amps, Common-Mode feedback loop stability.

Module:5 Stability analysis

Basic Concepts, Instability and the Nyquist Criterion, Stability Study for a Frequency-Selective Feedback Network, Effect of Pole Locations on Stability

7 hours

8 hours

8 hours

4 hours

Mo	dule:6	Frequency compensation			4 hours
Fre	quency (Compensation: Concepts and Tech	niques for Frequency Comp	pensation – l	Dominant
pol	e, Miller	Compensation, Compensation of	Miller RHP Zero, Nested M	filler, Comp	ensation of
two	stage O	P Amps.			
Mo	dule:7	Phase Locked Loops			4 hours
Pro	blem of	Lock acquisition, Phase Detector,	Basic PLL and its dynamics	s, Charge-pi	ımp PLL,
No	n-ideal e	ffects in PLL: PFD/CL non idealit	ies, Jitter, Delay Locked Lo	oop, Applica	tions.
				r	
Mo	dule:8	Contemporary issues:			2 hours
			Total Lectu	are hours:	45 hours
Tey	kt Book(s)			
1.	Behzad	Razavi, Design of Analog CMOS	Integrated Circuits, McGr	aw-Hill, Se	cond Edition,
	2017.				
2.	David	Johns and Ken Martin, Analog Ir	ntegrated Circuit Design, J	ohn Wiley	& Sons, Inc.,
	Second	Edition, 2012.			
Ref	erence l	Books			
1.	Phillip	E. Allen and Douglas R. Holberg	, CMOS Analog Circuit D	esign, Oxfo	rd University
	Press, I	JK, Second Edition, 2010.			
2.	R. Jaco	b Baker, CMOS Circuit Design	n, Layout and Simulation	n, IEEE Pre	ss Series on
	Microe	lectronic Systems, Wiley Publicat	ions, Third Edition, 2010.		
		valuation:Continuous Assessment			
		eminar / Challenging Assignment		[/] Innovative	ideas leading
		for industrial problems, Final Asse			
		llenging Experiments (Indicative			
1	-	is and Design of Common Source	-	inected	4 hours
		nd Suggest a Circuit to achieve hig			
2	•	is and Design of Common Gate A	1		4 hours
		t Source load. Justify the results in	n terms of input impedance	of the	
-	circuit.			•••	
3	•	is and Design of Simple Current	Mirror and Suggest a cir	cuit to	4 hours
4		ze the error in the output current.	A 1101 1.1 A .1 1		<i>c</i> 1
4		is and Design of Differential A	Amplifier with Active loa	ad and	6 hours
~		t Source Load.		:4	<u> </u>
5	•	is and Design of Cascode Amp		cuit to	4 hours
-		me Voltage Headroom Limitation.			0.1
6	Analys	is and Design of Two-Stage Opam			8 hours
N /	da - 6 T	abaatia m.Co.ntinue aa	Total Laboratory		30 hours
		aluation:Continuous assessment of	chanenging experiments /	rinal Assess	ment Test
(FA	,	lad by Poord of Studios	13-12-2015		
		led by Board of Studies		10 02 2014	5
Ар	provea b	y Academic Council	No. 40	18-03-2010)

Course Code	Course Title	LT	P	J	C
ECE5017	DIGITAL DESIGN WITH FPGA	2 0	2	4	4
Pre-requisite	Nil				
Course Objectives :					
The course is aimed	to				
1. understand the v	various abstraction levels in Verilog HDL and thus model tasks a	¢ fu	ncti	on	s at
behavioral level.					
	machines using D and JK Flip Flops and design the complex of	comł	oina	tio	nal
-	ogic circuits using various constructs in Verilog.				
	types programmable logic devices and building blocks of FP	GA	and	l t	hus
implement the d	esign using Xilinx and ALTERA FPGAs.				
Expected Course Outc					
	the student will be able to				
	ous abstraction levels in Verilog HDL.				
0	2. design finite state machine using D and JK Flip Flop.				
	l circuit using behavioural modelling.		- 1 - "		
0 1	blex combinational and sequential logic circuits using various cor	struc	ts 1	n	
Verilog.	The second se				
	grammable logic devices and various blocks exist in FPGA.				
	rchitectural and resource difference between ALTERA and Xilin	х.			
	design complex combinational and sequential circuits.				
o. develop and pro	totype digital systems design using FPGA.				
Module:1 Verilo	og HDL – Data Flow & Structural Modeling		6	ho	urs
	Ports and Modules – Operators - Gate Level Modeling - Data Flow	v Mo			
	ler Directives - Test Bench.			•	2
Module:2 State	Machine Design		4	ho	urs
Definition of state made	chines -State machine as a sequential controller- Analysis of s	tate	ma	chi	nes
using D and JK flip	-flops - Design of state machines- State table and State	assig	gnm	nen	t-
Transition/excitation ta	ble - excitation maps and equations - logic realization- Des	ign e	xai	np	les:
Sequence detector, Seria	al adder, Vending machine.				
	og HDL – Behavioral Modeling				urs
	leling- Procedural Assignment Statements- Blocking and	Non-	Blo	ock	ing
Assignments - Tasks & I	Functions - Useful Modeling Techniques.				
	og Modeling of Combinational Circuits		4	ho	urs
Behavioral, Data Flow a	and Structural Realization of Adders and Multipliers				
	og Modeling of Sequential Circuits				urs
	chronous FIFO – Single port and Dual port ROM and RAM - FS	ΜV	eril	log	
modeling of Sequence	detector - Serial adder - Vending machine.				
	A			1.	
	Architecture	Dec			urs
	le Logic Devices: PLA, PAL, CPLD - FPGA Architecture - Programmable Logic Blocks- Fabric and Architecture of FPGA.		,i af	1111	mg

1.	Ming-Bo Lin, Digital Systems Design and Practice: Using Verilog HDL and Space Independent Publishing Platform, Second Edition, 2015.	FPGAs, Create
2.	Michael D Ciletti, Advanced Digital Design with the Verilog HDL, Prentic Edition, 2011.	ce Hall, Second
Referen	nce Books	
1.	Wayne Wolf, FPGA Based System Design, Prentices Hall Modern Semico	nductor Design
	Series, 2011.	C
2.	Charles H Roth Jr, Lizy Kurian John and Byeong Kil Lee Digital System	s Design using
	Verilog, Cengage Learning, First Edition, 2016.	
Mode o	f Evaluation: Continuous Assessment Test -I (CAT-I), Continuous Assessment	Test -II (CAT-
II), Sen	inar / Challenging Assignments / Completion of MOOC / Innovative ideas lead	ling to solutions
for indu	strial problems, Final Assessment Test (FAT).	-
	Challenging Experiments (Indicative)	
1. 2. 3.	Many ink-jet printers have six cartridges for different colored ink: black, cyan, magenta, yellow, light cyan and light magenta. A multibit signal in such a printer indicates selection of one of the colors. Write a data flow Verilog model for a decoder for use in the inkjet printer described above. The decoder has three input bits representing the choice of color cartridge and six output bits, one to select each cartridge. Verify the output of the design using test bench by simulating in Modelsim Simulator. Implement the design in ALTERA DE2-115 Board and verify it's functionality. Write a behavioral Verilog code to divide the ALTERA DE2-115 Board clock frequency 50MHz by 40MHZ, 30MHz, 20 MHz, 10MHz. Display each of the output using LEDs available in the board.	4 hours 4 hours 4 hours
	day clock. It should display the hour (from 0 to 23) on the 7-segment displays HEX7-6, the minute (from 0 to 60) on HEX5-4 and the second (from 0 to 60) on HEX3-2. Use the switches SW15-0 to preset the hour and minute parts of the time displayed by the clock.	
4.	We wish to implement a finite state machine (FSM) that recognizes two specific sequences of applied input symbols, namely four consecutive 1s or four consecutive 0s. There is an input w and an output z. Whenever $w = 1$ or w = 0 for four consecutive clock pulses the value of z has to be 1; otherwise, z = 0. Overlapping sequences are allowed, so that if $w = 1$ for five consecutive clock pulses the output z will be equal to 1 after the fourth and fifth pulses. Design and Implement the design using DE2-115 Board.	8 hours
5.	Write a behavioral Verilog code to design FIFO with the following specification	10 hours

Xilinx and ALTERA FPGAs Module:7

Contemporary issues:

Module:8

Text Book(s)

2 hours Xilinx Virtex 5.0 Architecture - Xilinx Virtex VI Architecture - ALTERA Cyclone II Architecture -ALTERA Stratix IV Architecture.

Total Lecture hours:

2 hours

30 hours

d_in: input data; 8 bit width is con			
d_out: output data; 8 bit width is c	onsidered ·		
w_en: write enable signal			
r_en: read enable signal			
r_next_en: read next enable			
w_next_en: write next enable			
w_clk: write clock; 10 MHz for the	is design		
r_clk: read clock; 50 MHz for this	design		
w_ptr: write address pointer; 4 bit	to address depth of 16 \cdot		
r_ptr: read address pointer; 4 bit to	address depth of 16 \cdot		
ptr_diff: address pointer difference	; 4 bit width		
f_full_flag: FIFO full flag; asserted	d when FIFO is full ·		
f_empty_flag: FIFO empty flag; as	sserted when FIFO is empty		
Use Dual Port RAM available in	ALTERA IP library to realize	e the FIFO.	
Implement the design using ALTE	RA DE2-115 board.		
	Total Laborat	tory hours:	30 hours
Mode of Evaluation: Continuous assessm	ent of challenging experimen	nts / Final A	Assessment Test
(FAT).			
List of Projects (Indicative)			
1. Design MIPS 32-Bit RISC Processor	r and implement it using ALTE	ERA Cyclone	IV FPGA and
study about it's performance.			
2. Design a Reconfigurable FIR Filter a	and verify it's functionality thro	ough test ben	ch. Implement
the design using ALTERA Cyclone	IV FPGA.	-	_
3. Design and Implementation of Smar	t Traffic Light System for cong	gested four w	ay road using
ALTERA Cyclone IV FPGA.			
4. Design and Implementation of COR	DIC Algorithm using ALTERA	A Cyclone IV	FPGA.
Mode of Evaluation: Review I, II & III	-	-	
Decommonded by Decord of Studies	13-12-2015		
Recommended by Board of Studies	10 12 2010		

Pre-requisite	None	Syllabus version
		v.1.1
Course Objectives	3:	
The course is aimed	d to	
-	ndamentals of intrinsic, extrinsic semiconductors with carrier	concentration,
	hysics of various carrier current transport mechanisms	
	ed physics and modeling of PN Junction, MOS capacitors, ar	
3. Review and disc	uss in detail the short channel effects and the issues of UDSN	A transistors
Expected Course		
	ourse the student will be able to	1 / 1/1 1 1
-	sic semiconductors with specific carrier concentrations and, u	inderstand the band
	iagrams of semiconductors.	
	model the carrier transport mechanism in semiconductors.	
	nctions of given specifications	
4. Model MOS	1	
	ETs and model the MOSFETs	
6. Mitigate the sl	hort channel effects and design UDSM transistors	
Module:1 Semic	·	5 hours
	blids - Intrinsic and Extrinsic semiconductors - Direct and	
•	- Fermi distribution -Free carrier densities - Boltzmann s	tatistics - Thermal
equilibrium.		
Module:2 Carri	er Transport in Semiconductors	4 hours
	anisms: Drift current, Diffusion current - Mobility of carrier	
equations - Continu		is - Current density
equations contine		
Module:3 P-N J	unctions	5 hours
	m physics - Energy band diagrams - Space charge layers -	
-	d Potentials - p-n junction under applied bias - Sta	-
	-n junctions - Breakdown mechanisms.	C
	~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~	
Module:4 MOS	Capacitor	8 hours
Accumulation - De	pletion - Strong inversion - Threshold voltage - Contact po	tential - Gate work
function - Oxide an	d Interface charges - Body effect - C-V characteristics of MO	SC
Module:5 MOS	FETs and Compact Models	8 hours
	uration voltage - Sub-threshold conduction - Effect of gate a	-
	Compact models for MOSFET and their implementation in	SPICE: Level 1, 2
and 3 - MOS mode	l parameters in SPICE.	
	and Short Channel Effects	6 hours
-	- Channel length modulation - Punch-through - Hot ca	rrier degradation -
MUSPEI breakdov	wn - Drain-induced barrier lowering.	

Course Title

Physics of VLSI Devices

LT

P J C

3 0 0 0 3

Course code

ECE 5018

7 hours

2 hours

45 hours

Module:7 UDSM Transistor Design Issues

Effect of tox - Effect of high-k and low-k dielectrics on the gate leakage and Source and drain leakage - tunneling effects - Different gate structures in UDSM - Impact and reliability challenges in UDSM.

Module:8 Contemporary issues:

Total Lecture hours: Text Book(s)

- 1. Ben G. Streetman and S. Banerjee, Solid State Electronic Devices, Pearson Education, U.S, Seventh Edition, 2014.
- 2. J.P. Colinge and C. A. Colinge, Physics of Semiconductor Devices, Kluwer Academic Publishers, US, 2017.

Reference Books

- 1. Y.P. Tsividis and Colin McAndrew, Operation and Modelling of the MOS Transistor, Oxford University Press, US, Third Edition, 2011.
- 2. M K Achutan and K N Bhatt, Fundamental of Semiconductor Devices, McGraw Hill Education, US, 2017.

Mode of Evaluation: CAT / Assignment / Quiz / FAT

Recommended by Board of Studies	05-10-2017	
Approved by Academic Council	No. 47	05-10-2017

Course Code	Course Title	LTPJC
ECE5019	COMPUTER AIDED DESIGN FOR VLSI	3 0 0 0 3
Pre-requisite	Nil	
Course Object	ive :	
The course is a	imed to	
1. imbibe	the students with the fundamentals of graphs, the relevance and, their	applications
	design automation.	
2. introduc	e the students with relevant examples the estimation of computational	al complexity
and the	general classes of computational problems.	
3. explain	With relevant examples and algorithms demonstrate partitioning, fle	oor planning,
area rou	ting, clock routing and pin assignment of physical design flow	
-		
Expected Cour		
	e course students will be able to	
	ate the graphs for the given problems;	hma
	te and analyse the computational complexity of physical design algorit n a given design.	mns;
	and change the floorplans in an abstract manner and use computer alg	orithms to
-	rge and optimized floorplans	
	ptimized placements on the silicon chip and perform complex routing	ising
	ms and computer codes.	using
	clock trees to distribute the clock signals on the chip while satisfying v	various
-	nts like clock skew and wire length.	u 10 u 5
••••••••		
Module:1 In	troduction to course	5 hours
Y Chart- Phys	ical design top down flow- Review of graph theory: complete grap	h, connected
graph, sub grap	h, isomorphism, bi partite graph tree.	
Module:2 Co	omputational complexity of algorithms	4 hours
	- Class P- class NP -NP-hard- NP-complete.	•
	artitioning	6 hours
Problem form	alation- Group Migration Algorithm: Kernighan-Lin Simulated ann	ealing based
Partitioning.		
	oor planning	6 hours
•	algorithm- Wong-Liu algorithm (Normalized polish expression)- In	nteger Linear
Programming (ILP) based floor planning.	
		I
	n Assignment and Placement	7 hours
	nt: Concentric circle mapping, Topological pin assignment- Power	and ground
routing.		
Placement Wi	re length estimation models for placement - Quadratic placement- S	sequence pair
	Construction models for precenter Quantum precenter	1 1
technique.		
technique.	outing	8hours

Routing: Grid routing- Maze routing- Line Probe algorithms, Weighted Steiner tree approach. Global routing: Rectilinear routing(spanning tree, steiner tree)-Dijkstra's algorithm-routing by ILP Detailed routing: Problem formulation- Two layer channel routing : Left Edge algorithm, Dogleg router- Net Merge channel router - Three-layer channel routing - HVH, VHV router- Introduction to switch box routing.

Module:7 Clocking Tree Topologies

7hours

Clocking tree topologies: H-tree, Xtree- Method of Means and Medians (MMM)- recursive geometric matching- Elmore delay model to calculate skew- Buffer insertion in clock trees- Exact Zero skew clock routing algorithm. Clock mesh topologies: uniform and non-uniform mesh.

Mo	dule:8	Contemporary issues:			2hours
			Total	Lecture hours:	45hours
Tex	<u>kt Book(</u>				
1.		0	Igor L. Markov, JinHu,VLSI	Physical Design:	From Graph
	Partitio	ning to Timing Closure, S	Springer, 2011.		
2	H. Yo	suff and S.M. Sait, VI	SI Physical Design Automa	tion – Theory a	nd Practice,
	Cambri	dge India, 2010.			
3.	Sung k	Kyu Lim, Practical Probl	ems in VLSI Physical Design	n Automation, Sp	ringer India,
	2011.				
Ref	ference l	Books			
1.	S. Sridl	har, Design and Analysis	of Algorithms, Paperback – OU	JP, 2014.	
2.	John C	kyereAttia, PSPICE and	MATLAB for Electronics:	An Integrated Ap	proach,CRC
	Press, 2	2010.			
3.	Ganesh	M.Magar, Swati R.M	aurya Rajesh K.Maurya, Gra	aph Theory & A	Applications,
	Technie	cal Publications, 2016.			
4	Brian C	Christian and Tom Griffith	ns, Algorithms to Live By: The	e Computer Scien	ce of Human
	Decisio	ons, William Collins, 2017	7.		
Mo	de of Ev	valuation:Continuous Ass	essment Test -I (CAT-I), Co	ontinuous Assessn	nent Test –II
(CA	AT-II), S	eminar / Challenging Ass	signments / Completion of MO	OC / Innovative	deas leading
to s	olutions	for industrial problems, F	Final Assessment Test (FAT).		
Rec	commend	led by Board of Studies	13-12-2015		
App	proved b	y Academic Council	No. 40	18-03-2016	

Course Code	Course Title L T P J C
ECE5020	DSP ARCHITECTURES 2 0 0 4 3
Pre-requisite	Nil
•	
Course Objective:	
The course is aime	
1. Explore dif	ferent Digital Signal Processor (DSP) architectures and to design systems using
programma	
2. Improve sy	stem performance using different pipelining techniques, processor array and
systolic arra	ay.
3. Interface of	f memory and peripherals to a DSP; and acquire knowledge on different codec
implemente	d on DSP.
Expected Course	Outcome:
The students will b	e able to
1 11-416	
~	d use specific Digital Signal Processor for various applications.
	stem using programmable DSP.
	pipelining techniques to improve system performance.
4. Implement performanc	applications using processor array and systolic arrays to enhance the
-	e. blving memory and other interfaces to DSP.
Ũ	arious codecs on target DSPs.
0. Design of v	anous codecs on target DSFs.
Module:1 DSP 1	Integrated Circuits and VLSI Technologies 2hours
	gnal processors - Application specific IC's for DSP - DSP systems - DSP
	egrated circuit design.
system design - m	
Module ? Archi	tectures for programmable DSP 4 hours
	Il Features - DSP Computational Building Blocks - Bus Architecture and
Memory - Data	Addressing Capabilities - Address Generation Unit - Programmability and
	- Features for External Interfacing.
Module:3 Execu	Ition Control and Pipelining 4 hours
	- Interrupts - Stacks - Relative Branch support - Pipelining and Performance -
	Interlocking - Branching effects - Interrupt effects - Pipeline Programming
models.	
Module:4 Synth	esis of DSP Architectures 6 hours
	ach to DSP LSI - Circuit Synthesis - High Performance Data conversion
	Algorithms and Architectures - Hierarchical Design of Processor Arrays -
1	tack Filters - Wave-front Array Processors.
<u> </u>	
Module:5 Interf	facing Memory and I/O to DSP Processors 5 hours
	facing signals - Memory interface - Parallel I/O interface - Programmed I/O -
	-Direct memory access (DMA) A Multichannel buffered serial port (McBSP) -
McBSP Programn	ning.
	facing CODEC 3 hours
CODEC interface	circuit - CODEC programming - A CODEC-DSP interface example.

Module:7	Multiprocessor Systems	4hours
Architecture	s of Multiprocessors-Performance comparison of -Multiprocessor Structures.	
Module:8	Contemporary issues:	2hours
	Total Lecture hours:	30hours
Text Book	(s)	
1. Lars W	anhammer, DSP Integrated Circuits, Academic press, New York, 2011.	
2. Avtar S	Singh and S. Srinivasan, Digital Signal Processing, Thomson Publications, 20	012.
Reference	Books	
1. Phil L	apsley, Jeff Bier, AmitShoham, Edward A. Lee, DSP Processor Fun	damentals,
Archite	ectures & Features, Wiley-IEEE Press, First Edition, 2011.	
2. Peter F	irsch, Architectures for Digital signal processing, Wiley India, 2010.	
Mode of E	valuation: Continuous Assessment Test -I (CAT-I), Continuous Assessme	nt Test –II
	eminar / Challenging Assignments / Completion of MOOC / Innovative ide	eas leading
to solutions	for industrial problems, Final Assessment Test (FAT).	
List of Pro	jects (Indicative)	
1. Ima	ge Compression algorithm implementation in Programmable DSP.	
	ge processing algorithm implementations on FPGA.	
3. Tur	bo Decoder implementation.	
	RDIC Algorithm implementation in PDSP/FPGA/ASIC flow.	
	roved Adaptive filters.	
6. Imp	roved Median filters.	
Mode of Ev	aluation: Review I, II and III	
Recommen	ded by Board of Studies 13-12-2015	

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Recommended by Board of Studies	13-12-2015	
Approved by Academic Council	No. 40	18-03-2016

Course Code Course Title VLSI DIGITAL SIGNAL PROCESSING

Pre-requisite Nil

ECE5022

Course Objective :

The course aimed to:

- 1. Familiarise various representation methods of DSP algorithms, understand the significance of the iteration bound and to calculate the same for a given single-rate and/or multi-rate DFG.
- 2. Understand and apply the architectural transformation techniques such as retiming, unfolding and folding on a given DFG.
- 3. Introduce the algorithmic and numerical strength reduction methods for performance improvement.
- 4. Signify and calculate the effects of scaling and round-off noise for a given digital filter with limited word length.

Expected Course Outcome :

The students will be able to:

- 1. Compare various representation methods of DSP algorithms.
- 2. Find iteration bound of a given single and/or multi-rate DFG.
- 3. Understand and transform the given DFG using retiming with constraints.
- 4. Apply unfolding and folding transformations on the given DFG.
- 5. Understand and apply algorithmic and numerical strength reduction methods.
- 6. Understand and calculate scaling and round-off noise of the given digital filter with limited word length.

Module:1 | Introduction to Digital Signal Processing

5 hours Typical DSP Algorithms - DSP Application Demands and Scaled CMOS Technologies -Representations of DSP Algorithms - Data-Flow Graph Representations.

Module:2 | Iteration Bound

5 hours Introduction - Loop Bound and Iteration Bound - Algorithms for Computing Iteration Bound: Longest Path Matrix and Multiple Cycle Mean algorithms - Iteration Bound of Multi-rate Data Flow Graphs.

Module:3 | Pipelining, Parallel processing and Retiming

Pipelining and Parallel Processing - Introduction to Retiming - Definitions and Properties -Solving Systems of Inequalities - The Bellman-Ford Algorithm - The Floyd Warshall Algorithm-Retiming Techniques.

Module:4 Unfolding

Introduction, An Algorithm for Unfolding, Properties of Unfolding, Critical Path, Unfolding, and Retiming, Applications of Unfolding.

Module:5 | Folding

Introduction, Folding Transformation, Register Minimization Techniques, Register Minimization in Folded Architectures.

Module:6 | Algorithmic & Numerical Strength Reduction 7 hours Introduction to Algorithmic Strength Reduction, Cook-Toom Algorithm, Iterated Convolution, Convolution, Discrete Cosine Transform. Introduction to Cyclic Numerical Strength

8 hours

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6 hours

Reduction, Canonic Signed Digit Arithmetic, Sub-expression Elimination, Multiple Constant Multiplication, Sub-expression Sharing in Digital Filters.

Module:7 Scaling and Rounding Noise

6 hours

Introduction, Scaling and Rounding Noise, State Variable Description of Digital Filters, Scaling and Rounding Noise Computation, Rounding Noise in Pipelined IIR Filters.

Module:8 Contemporary issues:

				-
			Total Lecture:	45 hours
Tex	xt Book(s)			
1.		Signal Processing	Systems: Des	sign and
	Implementation, Reprint, Wiley, Inter So	cience, 2014.		
Ref	ference Books			
1.	John G. Proakis, Dimitris K Manolak	tis, Digital Signal Proce	essing: Principles	, Algorithms
	and Applications, Prentice Hall, Fourth	Edition, 2015.		
2.	Mohammed Ismail and Terri Fiez, Ana	alog VLSI Signal and Ir	formation Proces	sing,McGraw-
	Hill, 2014.			
3.	S.Y. Kung, H.J. White House, T. Kaila	th, VLSI and Modern Si	ignal Processing, I	PHI, 2010.
4.	S. K. Mitra, Digital Signal Processir	ng – A Computer Base	ed Approach, Fo	urth Edition,
	McGraw-Hill, 2010.			
Mo	de of Evaluation:Continuous Assessme	nt Test –I (CAT-I), Co	ontinuous Assess	ment Test –II
(CA	AT-II), Seminar / Challenging Assignme	ents / Completion of MC	DOC / Innovative	ideas leading
to s	olutions for industrial problems, Final A	ssessment Test (FAT).		_
Rec	commended by Board of Studies	13-12-2015		
App	proved by Academic Council	No. 40	18-03-2016	

Course Code	Course Title	L T P J C
ECE5023	MEMORY DESIGN AND TESTING	3 0 0 0 3
Pre-requisite	Nil	

Course Objectives :

The course is aimed at

- 1. Expounding the basics and detailed architecture of SRAMs and DRAMs.
- 2. model the memory fault and introduce the basic and advanced memory testing patterns.
- 3. Elaborate the reliability and radiation effect issues of semiconductor memories and present methods for radiation hardening.
- 4. Review and discuss high performance memory subsystems, advanced memory technologies and contemporary issues

Expected Course Outcome :

At the end of the course the student should be able to

- 1. Design SRAMs and DRAMs.
- 2. Design NVRAMs and Flash Memories.
- 3. Model memory faults, select suitable testing patterns and develop testing patterns.
- 4. Incorporate DFT and BIST techniques for semiconductor memory testing.
- 5. Improve the reliability of semiconductor memories, simulate and model radiation effects and, perform radiation hardening.
- 6. Contribute to the development of high performance memory subsystems and use advanced memory technologies.

Module:1 Volatile memories

SRAM - SRAM Cell structures, MOS SRAM Architecture, MOS SRAM cell and peripheral circuit operation, SOI technology, Advanced SRAM architectures and technologies, soft error failure in SRAM, Application specific SRAMs, DRAM - DRAM technology development, CMOS DRAM, DRAM cell theory and advanced cell structures, BICMOS DRAM, soft error failure in DRAM, Advanced DRAM design and architecture, Application specific DRAM.

Module:2 Non-volatile memories

Masked ROMs, High density ROM, PROM, Bipolar ROM, CMOS PROMS, EPROM, Floating gate EPROM cell, One time programmable EPROM, EEPROM, EEPROM technology and architecture, Non-volatile SRAM, Flash Memories (EPROM or EEPROM), advanced Flash memory architecture.

Module:3 | Memory Testing and Patterns

General Fault Modeling – Read Disturb Fault Model – Precharge Faults – False Write Through Data Retention Faults – Decoder Faults. Megabit DRAM Testing Nonvolatile Memory Modeling and Testing-IDDQ Fault Modeling and Testing Application Specific Memory Testing - Zero/one Pattern – Exhaustive Test Patterns – Walking, Matching and Galloping – Pseudo Random Pattern – CAM pattern.

Module:4 Design For Test and BIST

RAM Built-In Self – Test (BIST)-Weak Write Test mode – Bit Line Contact Resistance – PFET Test – Shadow Write and Shadow Read.

Reliability and Radiation Effects Module:5

7 hours

4hours

5 hours

7 hours

18-03-2016

Alberto Bosio, Luigi Dilillo, Patrick Girard, Serge Pravossoudovitch, Arnaud Virazel, Advanced Test Methods for SRAMs: Effective Solutions for Dynamic Fault Detection in Nanoscaled Technologies, Springer, 2010. Hao Yu and YuhaoWang, Design Exploration of Emerging Nano-scale Non-volatile Memory, 2. Springer, 2014. Takayuki Kawahara (Editor), Hiroyuki Mizuno (Editor), Green Computing with Emerging 3.

Mode of Evaluation: Continuous Assessment Test -I (CAT-I), Continuous Assessment Test -II (CAT-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative ideas leading

13-12-2015

No. 40

Memory: Low-Power Computation for Social Innovation, Springer, 2012.

to solutions for industrial problems, Final Assessment Test (FAT).

2. Roberto Gastaldi and Giovanni Campardo In Search of the Next Memory: Inside the Circuitry from the Oldest to the Emerging Non-Volatile Memories, Springer, 2017.

- 1. A. K.Sharma, Advanced Semiconductor Memories: Architecture, Design and Applications, John Wiley, 2014.

- **Text Book(s)**
- **Total Lecture hours:** 45 hours

High-Density Memory Packaging Technologies, Ferroelectric Random Access Memories (FRAMs)- Analog Memories-Magneto-resistive Random Access Memories (MRAMs)-Experimental Memory Devices Memory Hybrids and MCMs (2D)- Memory Stacks and MCMs

General Reliability Issues-RAM Failure Modes and Mechanism-Nonvolatile Memory Reliability-Design for Reliability Radiation Effects-Single Event Phenomenon (SEP)- Radiation Hardening Techniques Radiation Hardening Process and Design Issues-Radiation Hardened Memory

Reference Books

1.

Characteristics.

(3D)-Memory MCM Testing and Reliability.

Module:7 | Advanced Memory Technologies

Module:8 Contemporary issues:

Recommended by Board of Studies

Approved by Academic Council

DRAMs, Embedded Memories.

2 hours

Module:6 | High-Performance Subsystem Memories Hierarchical Memory Systems, Memory-Subsystem Technologies, High-Performance Standard

7 hours

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Course Code	Course Title	L T P J C
ECE5024	IC TECHNOLOGY	3 0 0 0 3
Pre-requisite	Nil	

Course Objective :

The course is aimed to

- 1. Introduce the process involved in semiconductor manufacturing and fabrication.
- 2. Model the oxidation growth rate & to understand oxidation process and the process of diffusion and to expound the Ion Implantation process.
- 3. Explain the thin film deposition process and review the difference between MOS and Bipolar Process Integration.

Expected Course Outcome :

At the end of the course the student will be able to

- 1. Understand the process involved in semiconductor manufacturing and fabrication.
- 2. Understand the various lithography techniques used for pattern transfer.
- 3. Model the oxidation growth.
- 4. Model the diffusion mechanism in semiconductors.
- 5. Understand the process involved in thin film deposition.
- 6. Analyse the difference between MOS and Biploar Process.

Module:1 Crystal Growth

Introduction to Semiconductor Manufacturing and fabrication, Clean Room types and Standards, Physics of the Crystal growth, wafer fabrication and basic properties of silicon wafers.

Module:2 Lithography:

The Photolithographic Process, Photomask Fabrication, Comparison between positive and negative photoresists, Exposure Systems, Characteristics of Exposure Systems, E-beam Lithography, X- ray lithography.

Module:3 Thermal Oxidation of Silicon:

The Oxidation Process, Modeling Oxidation, Masking Properties of Silicon Dioxide, Technology of Oxidation, Si-SiO2 Interface.

Module:4 Diffusion and Ion Implantation:

The Diffusion Process, Mathematical Model for Diffusion, Constant-, The Diffusion Coefficient, Successive Diffusions, Diffusion Systems, Implantation Technology, Mathematical Model for Ion Implantation, Selective Implantation, Channeling, Lattice Damage and Annealing, Shallow Implantations.

7 hours

5 hours

6 hours Dioxide,

7 hours

C		echnology, Silicides and Multilayer-Contact Technology, Copper Inte	
		e Processes, Wafer Thinning and Die Separation, Die Attachment, V	
	anaseen ackages,		wite boliding,
	ierages,		
M	odule:6	MOS Process Integration:	5 hours
		S Device Considerations, MOS Transistor Layout and Design Rules, Com	plementary
		OS) Technology.	1 2
	X		
Me	odule:7	Bipolar Process Integration:	6 hours
Iso	lation T	echniques in BJT fabrication, Advanced Bipolar Structures, Other Bip	polar Isolation
Te	chniques	. Deep Submicron Processes, Low-Voltage/Low-Power CMOS/BiCM	OS Processes.
Fut	ture Trer	ds and Directions of CMOS/BiCMOS Processes.	
-			
M	odule:8	Contemporary issues:	2 hours
Me	odule:8	Contemporary issues:	2 hours
Mo	odule:8	Contemporary issues: Total Lecture hours:	2 hours 45 hours
	odule:8 xt Book	Total Lecture hours:	
	xt Book	Total Lecture hours:	
Te	xt Book	Total Lecture hours:	45 hours
Te 1. 2.	xt Book	Total Lecture hours: (s) ze, VLSI technology, Tata McGraw-Hill, Second Edition, 2017. neger, Introduction to microelectronic fabrication, Prentice Hall, Second H	45 hours
Te 1. 2.	xt Book S.M. S R.C. Ja ference	Total Lecture hours: (s) ze, VLSI technology, Tata McGraw-Hill, Second Edition, 2017. neger, Introduction to microelectronic fabrication, Prentice Hall, Second H	45 hours Edition, 2013.
Te 1. 2. Re	xt Book S.M. S R.C. Ja ference S.A. (Total Lecture hours: (s) ze, VLSI technology, Tata McGraw-Hill, Second Edition, 2017. neger, Introduction to microelectronic fabrication, Prentice Hall, Second H Books	45 hours Edition, 2013.
Te 1. 2. Re	xt Book S.M. S R.C. Ja ference S.A. C Univer	Total Lecture hours: (s) ze, VLSI technology, Tata McGraw-Hill, Second Edition, 2017. neger, Introduction to microelectronic fabrication, Prentice Hall, Second H Books Campbell, The science and engineering of microelectronics fabrication	45 hours Edition, 2013. ation, Oxford
Te 1. 2. Re 1.	xt Book S.M. S R.C. Ja ference S.A. O Univer Simon	Total Lecture hours: (s) ze, VLSI technology, Tata McGraw-Hill, Second Edition, 2017. neger, Introduction to microelectronic fabrication, Prentice Hall, Second H Books Campbell, The science and engineering of microelectronics fabrication sity Press, UK, Second Edition, 2012.	45 hours Edition, 2013. ation, Oxford y, 2011.

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Thin film deposition, contacts, packaging and yield:

to solutions for industrial problems, Final Assessment Test (FAT).

Recommended by Board of Studies

Approved by Academic Council

Module:5

Course Code	Course Title	L T P J C
ECE5025	SYSTEM ON CHIP DESIGN	3 0 0 0 3
Pre-requisite	Nil	
Course Objective		
The course is aime		
	ng design, optimization, and programing a modern System-on-a-Cl	-
Ũ	SoC design with on-chip memories and communication networks,	1/0
interfacin	g. hem understand about signal integrity aware SoC design and Sched	huling
algorithm		uning
argorithin		
Expected Course	Outcome :	
	ourse the student will be able to	
1. Demonstrat	te an ability to identify, formulate and treat complex issues in the	e field of
system-on-	chip from a holistic perspective.	
	e performance of SoC based design by various advanced technique	es.
	emC for system design.	
	nnection structures in a SoC / NoC based system design.	
	c timing analysis for a SoC based design.	1 1.
6. Analyse the	e cause and eliminate the issues relevant to signal integrity and sch	eduling.
Module:1 Intro	duction	3 hours
	present-day SoC - Design issues of SoC- Hardware-Software Co	
Libraries – EDA T		design core
Module:2 Desig	n Methodology for Logic, Memory and Analog Cores	6 hours
	- guidelines for design reuse - Introduction- Efficiency of applicat	ion specific
	rchitectures for HW/SW partitioning -System Integration, Embedd	led memories
 design methodole 	ogy for embedded memories – Specification of analog cores.	
	duction to System C for SoC Design	7 hours
	System Partitioning- Co-simulation, Co-synthesis & Co-verification and Co-simulation.	on –SystemC
and Co-specificatio		
Module:4 SoC a	and NoC Interconnection Structures	7 hours
		, nours
SoC Interconnecti	on Structures- Bus-based Structures- AMBA Bus.Network or	h Chip -NoC
	ructures-Topologies- routing- flow control- network components(1
network interface,	Links).	
		_
	for SoC Design	7 hours
• •	its Timing Optimization- Slow to High and High to low frequency	
• • • •	path- Latch time borrowing- Interface Logic Model design and ana	alysis for SoC
design.		
Modulo:6 Sim	I Integrity Awaro SoC design	7 hours
Module:6 Signa	Il Integrity Aware SoC design verview- EMI (Electro Magnetic Interference) and its protection-	7 hours

Signal Integrity overview- EMI (Electro Magnetic Interference) and its protection- ESD and its Protection- Delay- Noise- glitches and its protection- Transmission lines- ringing. Crosstalk and

Glitch analysis-Types of Glitches- Glitch Threshold and propagation- Noise Accumulation with Multiple aggressor- Aggressor timing correlation- Crosstalk Delay analysis -Timing Verification using crosstalk delay-Positive and Negative crosstalk- aggressor victim timing correlationaggressor victim functional correlation.

Module:7 Scheduling

6 hours

Introduction and need for HLS- Major steps-Scheduling and Allocation- Binding/Assignment-Concept of Scheduling, Heuristic Scheduling Algorithm.

Mo	dule:8	Contemporary issues:		2 hours
			Total Lecture hours	45 hours
Tey	t Book(s)		·
1.	Michae	l J. Flynn, Wayne Luk,Con	nputer System Design: System on chip,Wi	ey-Blackwell,
		dition, 2011.		
2.			Nanometer design – A practical approach,	Springer, First
	Edition			
-	erence l			
1.		Ayala,Communication Arch	nitectures for Systems-on-Chip, CRC Press,	First Edition,
	2011.			
2.	U	6 6	oud, Nur A. Touba, System-on-Chip Test	Architectures:
			Aorgan Kaufmann, First Edition, 2010.	
3.			Multiprocessor Systems-on-Chips (System	ns on Silicon
	Series),	, Morgan Kaufmann, First Ec	lition, 2010.	
Mo	de of Ev	valuation:Continuous Assess	ment Test -I (CAT-I), Continuous Assess	ment Test -II
`	, .	6666	ments / Completion of MOOC / Innovative	ideas leading
to s	olutions	for industrial problems, Fina	l Assessment Test (FAT).	
Rec	commend	led by Board of Studies	13-12-2015	
Ap	proved b	y Academic Council	No. 40 18-03-2016	

Course Code	Course Title	T P J C
ECE5026	SYSTEM DESIGN WITH FPGA	2 0 0 4 3
Prerequisite	Nil	
Course Objecti		
This course i		
	ne fundamental concepts of C language.	
	the architecture of NIOS II soft core processor and the variou	is peripheral
	s used for system design.	
-	nt the interconnect fabrics for the system and to design the system u	sing NIOS II
Soft core	Processor.	
Expected Cours	sa Autcoma ·	
	n of the course the student will be able to:	
1	nd the concepts of C language.	
	nd the NIOS II soft core processor architecture.	
	the usage of various peripheral interfaces for system design.	
	system by choosing suitable interconnect fabrics.	
	ne system using NIOS II soft core processor.	
	e system by using IP block.	
7. Design a	nd develop embedded synthesis using FPGA.	
	sic C Concepts	5 hours
Loops, Arrays, s	tructures, pointers, functions, linked list	
	t Core Processor	5 hours
Nios II Processo	r – Configurability Features – Processor Architecture-Instruction set	
Module:3 Per	in hovel Interferen	5 hours
	Tipheral Interfaces 32, SDRAM, SRAM Controller, VGA, Audio and Video, PIO, Externa	
and IrDA	52, SDRAM, SRAM Controller, VOA, Audio and Video, FIO, Externa	al Dus blidge
Module:4 NI	OS II programming for peripheral Interfaces	4 hours
	32, SDRAM, SRAM, VGA, Audio, IrDA.	
	erconnect Fabrics	3 hours
	Fabric Interconnect - Implementation and Functions- Integr	ated Design
Environment		
	stem Design	4 hours
I rame light Cor	ntroller, Real Time Clock - Interfacing using FPGA: VGA, , LCD, Ca	mera
Module:7 IP	Block Implementation	2 hours
	lgorithm, Colour and Brightness Enhancement algorithm	_ H0415
Module:8 Co	ntemporary issues:	2 hours
	• • I	-
	Total Lecture hours:	30 hours

Text Book(s)

1. ZainalabedinNavabi, "Embedded Core Design with FPGAs", TATA McGraw Hill Ltd, 2011.

2. Paul J. Deitel, Harvey M. Deitel, "C: How to Program", Pearson Education, 2012

Reference Books

1 NIOS II Handbook, 2014.

2 T.N.Padmanabhan, ThirupuraSundari, "Design Through VerilogHDL", Wiley Student Edition, 2010.

Mode of Evaluation:Continuous Assessment Test –I (CAT-I), Continuous Assessment Test –II (CAT-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative ideas leading to solutions for industrial problems, Final Assessment Test (FAT).

TypicalProjects

- 1. Implementation of edge detection algorithm
- 2. Implementation of self-guided vehicle.
- 3. Implementation of smart home system
- 4. Implementation of Health Monitoring System
- 5. Implementation of Music Synthesizer.

Mode of Evaluation: Review I, II and III

mode of D valuation. Review 1, 11 and 111		
Recommended by Board of Studies	13-12-2015	
Approved by Academic Council	No. 40	18-03-2016

Course Code	Course Title	LT	ΡJ	С
ECE5027	ADVANCED COMPUTER ARCHITECTURE	3 0	0 0	3
Pre-requisite	Nil			
Course Objective				
The course is aime				
	idvanced concepts of computer architecture.		1	
	owledge on various interconnect topology for multiprocessor syst	em a	nd	
1	pelining techniques. ling different memory hierarchy for multiprocessor and multicom	nutor	aveta	m .a
5. Understand	mig unreferit memory merarchy for multiprocessor and multicomp	Juter	syste	IIIS.
Expected Course	Outcomes:			
	ourse the student will be able to:			
1. Understand	I the architecture of the various multiprocessors and multicompute	er.		
	ssible parallel execution at hardware and software level.			
	uired static or dynamic interconnect network for a multiprocessor	syste	m.	
4. Apply diffe	erent pipelining techniques to reduce computation time.			
5. Analyse the	e various memory design for multiprocessor and multicomputer.			
6. Design sca	lable parallel architecture for multiprocessor system.			
	llel computer models			ours
	omputing - Classification of parallel computers - Multiparallel computers - Multiparallel computers.	roces	sors	and
Module:2 Prog	ram and network properties		7 h	ours
Program partition	Ilelism - Data and resource Dependences - Hardware and softwar ing and scheduling - Grain Size and latency - Program flow ta flow - Data flow Architectures.			
Module:3 Syste	m Interconnect Architectures		7 he	ours
Networks - Multip	es and routing - Static interconnection Networks - Dynamic is rocessor system Interconnects - Hierarchical bus systems - Cross - Multistage and combining network.			
Module:4 Pipel	ining		7 h	ours
Linear pipeline p Mechanisms for	processor - nonlinear pipeline processor - Instruction pipel instruction pipelining - Dynamic instruction scheduling - Bra h prediction - Arithmetic Pipeline Design		Desig	n -
Module:5 Mem	ory Hierarchy Design		6 h	ours
	cache performance - reducing miss rate and miss penalty - m	ultile		
	memory organizations - design of memory hierarchies.			
Module:6 Share	ed Memory Architectures		7 hou	irs
Symmetric shared	l memory architectures - distributed shared memory architec	tures	- c	ache
coherence protoco	els - scalable cache coherence - directory protocols - memory b based directory protocols.			
·				
Module:7 Mult	iprocessor Architectures		6 he	ours

	-	nal models - An Argument for es - Benchmark Performances.	r parallel Architectures -	- Scalability	of Parallel
Mo	dule:8	Contemporary issues:			2 hours
			Total Leo	cture hours:	45 hours
Tex	xt Book(s)			
1.		wang, NareshJotwani, Advanced nmability,Tata McGraw Hill Educ	1		•
Ref	ference I	Books			
1.		. Hennessy, David A. Patterson, n Kaufmann, Fifth Edition, 2011.	Computer Architecture: A	Quantitative	e Approach,
2.		ima, Terence Fountain, PeterrKar Approach, Pearson, 2014.	rsuk Advanced computer A	Architectures	– A Design
Mo	–	valuation:Continuous Assessment	Test –I (CAT-I) . Continu	ous Assessm	ent Test –II
		eminar / Challenging Assignments			
		for industrial problems, Final Asse	1		
		led by Board of Studies	13-12-2015		
		y Academic Council	No. 40	18-03-2016	

Explore the working principles of interface electronics electronics electronic (eq	
temperature sensors.	
ted Course Outcome :	
he completion of the course, students will be able to:	
Understand the Micro and Smart Systems.	
Identify MEMS materials and Properties.	
Understand the fabrication process flow for Microsystems.	
Classify and Comprehend different types of Sensors and Actuators.	
Explain about the wide applications of Microsensors.	
Understand the basic Interface Circuits.	
Understand the approach in design of Sensor Interface circuits.	
	21
le:1 Introduction to Micro and Smart Systems	3 hours
systems and scaling law, MEMS & Micro machines, Evolution of Microsystems,	Silicon and
licon Micro and Smart Systems, Market for Microsystems.	
le:2 Microsystem Materials and Properties	3 hours
als - Silicon, Silicon oxide and nitride, Thin Metal films (Cr, Au, Ti, Pt), Polymo	
A, PDMS), Glass and Quartz.	ers (500,
ant material properties-Young modulus, Poisson's ratio, density, piezoresistive	acofficients
Thermal Conductivity, Material Structure.	coefficients,
Thermal Conductivity, Material Structure.	
le:3 Micro System Technology	5 hours
Crystal Silicon Growth, Wafer Cleaning, Oxidation, Diffusion, Ion implant	
Electroplating, Lithography, Bulk Micromachining, Surface Micromachin	
ig and Packaging.	ling, LION,
le:4 Introduction to Sensors and Actuators	4 hours
ostatic, Piezoelectric, Piezoresistive, Electromagnetic, Thermo pneumatic, Sha	
Thermoelectric, Optical and Resonant.	tpe Memory
Thermoelectre, Optical and Resonant.	
le:5 Applications of Micro Devices	4.1
ial and Automotive Applications: Pressure Sensors, Accelerometers, Gas Se	4 hours
s, Gyroscopes, Micro mixer, Micro Valve, Micro Pump, Micro heater.	4 hours
s, Gyroscopes, where mixer, where varve, where rump, where heater.	
mmunication Applications: Imaging and Displays Fiber ontic communication d	ensors, Flow
mmunication Applications: Imaging and Displays, Fiber optic communication d and Smart Systems 2 Biomedical Applications: Micro & Nano Cantiley	ensors, Flow levices.
and Smart Systems -2. Biomedical Applications: Micro & Nano Cantileve	ensors, Flow levices. ers, Glucose
and Smart Systems -2. Biomedical Applications: Micro & Nano Cantileves, In Vitro and In Vivo Diagnostics.RF Applications – Switches, Phase Shifters	ensors, Flow levices. ers, Glucose
and Smart Systems -2. Biomedical Applications: Micro & Nano Cantileve	ensors, Flow levices. ers, Glucose
and Smart Systems -2. Biomedical Applications: Micro & Nano Cantileves, In Vitro and In Vivo Diagnostics.RF Applications – Switches, Phase Shifters	ensors, Flow levices. ers, Glucose
and Smart Systems -2. Biomedical Applications: Micro & Nano Cantileves, In Vitro and In Vivo Diagnostics.RF Applications – Switches, Phase Shifters	ensors, Flow levices. ers, Glucose , Resonators
and Smart Systems -2. Biomedical Applications: Micro & Nano Cantileves, In Vitro and In Vivo Diagnostics.RF Applications – Switches, Phase Shifters	ensors, Flow levices. ers, Glucose
and Smart Systems -2. Biomedical Applications: Micro & Nano Cantileves, In Vitro and In Vivo Diagnostics.RF Applications – Switches, Phase Shifters	ensors, Flow levices. ers, Glucose , Resonators

Expected (

Course Code

ECE5028

Pre-requisite

Course Objective :

fabricate it.

After the co

1. Und

Nil

Microsensors and actuators.

The course is aimed to

- 2. Iden
- 3. Und
- 4. Clas
- 5. Exp
- 6. Und
- 7. Und

Module:1

Microsyster Non-silicon

Course Title

MICROSENSORS AND INTERFACE ELECTRONICS

1. Introduce various types of Microsensors & micro actuators corresponding materials to

2. Make them Understand the concepts of Microsystem technologies used for realizing

3. Explore the working principles of interface electronics circuits for resistive, capacitive and

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Module:2

Materials -PMMA, PD

Important n TCR, Therr

Module:3

Single Crys CVD, Elec Bonding an

Module:4

Electrostatio Alloy, Ther

Module:5

Industrial a sensors, Gy

Telecommu

Micro and sensors, In and Varacto

Mo	odule:6	Interface Circuits	5 hours
In	terface c	ircuits for Resistive, Capacitive and Temperature Sensors	
		Voltage and Current - Mode Approach in Sensor Interfaces Design	4 hours
	0	ode Approach in Sensor Interfaces Design, DC & AC excitation for resisti	ve sensors,
		sensor interfacing, temperature sensor interfaces.	
		11 0 7	oltage for
Re	esistive/C	Capacitive Sensors, DC-Excited Resistive Sensor Interface.	
Mo	odule:8	Contemporary issues:	2 hours
			20.1
		Total Lecture hours:	30 hours
Te	xt Book(
1.		dou, Fundamentals of Microfabrication and Nanotechnology, CRC Pre-	ess, Third
	Edition		
2.		a De Marcellis, Giuseppe ferri, Analog circuits and systems for voltage-	mode and
		-mode sensor interfacing applications, Springer, 2011.	
	ference]		
1.		aluf, K Williams, An Introduction to Microelectromechanical	Systems
2		ering, Artech House Inc, Second Edition, 2004	
2.		uria, Microsystem Design, Springer Publisher, 2007.	- 2005
3.		ngBao, Analysis and Design Principles of MEMS Devices, Elsevier Scienc	e, 2005.
4.		vacs, Micromachined Transducers Sourcebook, McGraw-Hill, 1998	ant Test II
		valuation: Continuous Assessment Test –I (CAT-I) ,Continuous Assessm Geminar / Challenging Assignments / Completion of MOOC / Innovative i	
		for industrial problems, Final Assessment Test (FAT).	deas leading
		jects (Indicative)	
		ign of Piezoelectric cantilever for energy harvesting applications.	
		t detection using accelerometer and gyroscope.	
		ign of Silicon pressure sensors for car tire pressure monitoring.	
		AS pressure sensor for disposable blood pressure sensors.	
		AS grippers for the micromanipulation of biological cells.	
		rmoactuator switches for optical signal control.	
		ign of Gas sensors for automobiles.	
Mo	de of Ev	aluation:Review I, II & III	
Da	ommon	ded by Board of Studies 13, 12, 2015	

Recommended by Board of Studies	13-12-2015	
Approved by Academic Council	No. 40	18-03-2016

A Handle design complexity ensure reliable operation and achieve short	time to market
4. Handle design complexity, ensure reliable operation, and achieve short	inne-to-market
using various testing methodologies.	
Expected Course Outcome :	
After completion of the course students will be able to:	
1. Model different fault models.	
2. Simulate faults and generate test patterns for combinational circuits.	
3. Apply scan based testing.	
4. Recognize the BIST techniques for improving testability.	
5. Understand boundary scan based test architectures.	
6. Analyse and apply the test vector compression techniques for memory redu	ction and fault
diagnosis.	
5	
Module:1 Fault Modelling	6hours
Importance of Testing - Testing during the VLSI Lifecycle - Challenges in the VLS	SI Testing: Test
Generation - Fault Models - Levels of Abstraction in VLSI Testing - Historical R	
Test Technology - Functional Versus Structural Testing - Levels of Fault M	Aodels - Fault
Equivalence - Fault Dominance - Fault Collapsing - Check point Theorem - Delay I	Fault.
Module:2 Fault Simulation and Test Generation	7hours
Fault Simulation: Serial, Parallel, Deductive, Concurrent - Combinational Test	Generations -
ATPG for Combinational Circuits - D-Algorithm - Testability Analysis - SCOA	P measures for
Combinational Circuits	
Module:3 Scan based Testing	7hours
Design for Testability Basics - Ad Hoc Approach - Structured Approach - Scan	
Scan Architectures - Scan Design Rules - Scan Design Flow - Special Purpose	Scan Designs -
RTL Design for Testability.	
	-
Module:4 Built-in Self-Test	7hours
BIST Design Rules - Test Pattern Generation - Exhaustive Testing - Pseudo-Ran	-
Pseudo-Exhaustive Testing - Delay Fault Testing - Output Response Analysis	- Logic BIST
Architectures - BIST Architectures for Circuits with and without Scan Chains	
Module:5 Boundary scan and Core based Testing	5hours
Digital Boundary Scan (IEEE Std. 1149.1): Test Architecture and Operations -	-
Support with Boundary Scan - Board and System-Level Boundary-Scan Control Ar	chitectures.
	58
	50

Course Code Course Title Т P J С L ECE5029 VLSI TESTING AND TESTABILITY 3 0 0 0 3 Pre-requisite Nil

Course Objective :

The course is aimed to

- 1. Model and simulate different types of faults in digital circuits at the gate level.
- 2. Establish equivalence and dominance relationships of faults in a circuit.
- 3. compare automatic test pattern generation algorithms with respect to search space, speed, fault coverage and other criteria.

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Module:6	Test Compression and Compa	ction	6hours
Test Stimul	us Compression: Code-Based Sch	emes, Linear-Decompres	ssion-Based Schemes - Tes
Response C	ompaction.	_	
Module:7	Fault Diagnosis		5hours
Dictionary I	Based and Adaptive fault diagnosis	5.	
-			
Module:8	Contemporary issues:		2hours
	Total Lecture hours:		45hours
Text Book (s)		
1. Z.Nava	bi, Digital System Test and Testal	ble Design, Springer, 201	1.
•			
1. Laung-	Terng Wang, Cheng-Wen Wu,	and Xiaoqing Wen,	VLSI Test Principles and
0	ectures, The Morgan Kaufmann, 20	1 0	
	valuation:Continuous Assessment		nuous Assessment Test –I
	eminar / Challenging Assignments		
	for industrial problems, Final Asse	1	
	led by Board of Studies	13-12-2015	
	y Academic Council	No. 40	18-03-2016

Course code	Course Title	LTPJC
ECE 5030	Scripting languages for VLSI design automation	20203
Pre-requisite	None	Syllabus version
		v. 1.0
Course Objectiv		
The course is ain		
	scripts in the LINUX environment.	
	the principles of Scripting Languages like Perl, TCL and Python	
3. To write	the scripts for automation using the languages like Perl, TCL and	d Python.
Expected Cours	course the students will be able to	
	LINUX environment.	
	the PERL scriptts	
1	the TCL & TK scripts for automation	
1	the python scripts for automation	
	ipts for a given EDA design automation	
2	- <u>r</u>	
Module:1 LIN	NUX Basics	3 hours
	Linux, File System of Linux, General usage of Linux Kernel an	
	group, Permissions for file, directory and users, Searching a	
zipping and unzi		
Module:2 PE	RL Basics	5 hours
History and Con	cepts of PERL - Scalar Data - Arrays and List Data - Control s	structures – Hashes -
	ular Expressions – Functions - Miscellaneous control structures	
Basics I/O - Reg	ular Expressions – Functions - Miscellaneous control structures	- Formats.
Basics I/O - Reg Module:3 Adv	ular Expressions – Functions - Miscellaneous control structures vanced Topics in PERL	- Formats. 4 hours
Basics I/O - Reg Module:3 Adv	ular Expressions – Functions - Miscellaneous control structures	- Formats. 4 hours
Basics I/O - Reg Module:3 Adv Directory access	ular Expressions – Functions - Miscellaneous control structures vanced Topics in PERL - File and Directory manipulation - Process Management - Pack	- Formats. 4 hours kages and Modules.
Basics I/O - Reg Module:3 Adv Directory access Module:4 TC	ular Expressions – Functions - Miscellaneous control structures vanced Topics in PERL - File and Directory manipulation - Process Management - Pack L Basics	- Formats. 4 hours kages and Modules. 4 hours
Basics I/O - Reg Module:3 Adv Directory access Module:4 TC An Overview of	ular Expressions – Functions - Miscellaneous control structures vanced Topics in PERL - File and Directory manipulation - Process Management - Pack L Basics TCL and Tk -Tcl Language syntax – Variables – Expressions –	- Formats. 4 hours 4 ages and Modules. 4 hours 4 hours
Basics I/O - Reg Module:3 Adv Directory access Module:4 TC An Overview of	ular Expressions – Functions - Miscellaneous control structures vanced Topics in PERL - File and Directory manipulation - Process Management - Pack L Basics	- Formats. 4 hours 4 ages and Modules. 4 hours 4 hours
Basics I/O - Reg Module:3 Adv Directory access Module:4 TC An Overview of – procedures - En	ular Expressions – Functions - Miscellaneous control structures vanced Topics in PERL - File and Directory manipulation - Process Management - Pack L Basics TCL and Tk -Tcl Language syntax – Variables – Expressions – rrors and exceptions - String manipulations.	- Formats. 4 hours (ages and Modules) 4 hours Lists - Control flow
Basics I/O - RegModule:3AdvDirectory accessModule:4TCAn Overview of– procedures - EModule:5Ad	ular Expressions – Functions - Miscellaneous control structures vanced Topics in PERL - File and Directory manipulation - Process Management - Pack L Basics TCL and Tk -Tcl Language syntax – Variables – Expressions – rrors and exceptions - String manipulations. vanced Topics in TCL	- Formats. 4 hours (ages and Modules) 4 hours Lists - Control flow
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Basics I/O - Reg Module:3 Adv Directory access Module:4 TC An Overview of procedures - Ex Module:5 Ad Accessing files- Module:6 Module:6 Pyt Introduction to Modules Module:7 Ad	ular Expressions – Functions - Miscellaneous control structures vanced Topics in PERL - File and Directory manipulation - Process Management - Pack L Basics TCL and Tk -Tcl Language syntax – Variables – Expressions – rrors and exceptions - String manipulations. vanced Topics in TCL - Processes. Applications - Controlling Tools - Basics of Tk. Ehon Basics Python – Using Python interpreter – Control flow Tools – vanced Topics in Python t – Errors and Exceptions – Classes – Brief tour on standard libra	- Formats. 4 hours A hours
Basics I/O - Reg Module:3 Adv Directory access Module:4 TC An Overview of procedures - Ex Module:5 Ad Accessing files- Module:6 Module:6 Pyt Introduction to Modules Module:7 Ad	ular Expressions – Functions - Miscellaneous control structures vanced Topics in PERL - File and Directory manipulation - Process Management - Pack L Basics TCL and Tk -Tcl Language syntax – Variables – Expressions – rrors and exceptions - String manipulations. vanced Topics in TCL - Processes. Applications - Controlling Tools - Basics of Tk. thon Basics Python – Using Python interpreter – Control flow Tools – vanced Topics in Python t – Errors and Exceptions – Classes – Brief tour on standard libra ontemporary issues:	- Formats. 4 hours ages and Modules. 4 hours 4 hours

1.	Guido van Rossum Fred L. Drake, Jr., editor, "Python Tutorial Release 3.2.3", 2012.					
2.	Larry Wall, Tom Christiansen, John Orwant, "Programming PERL", Oreilly Publications,					
	Fourth Edition, 2012.					
3.	John K. Ousterhout, Ken Jones, "Tcl and the Tk Toolkit", Pearson Education, Second					
	Edition, 2010.					
Мос	le of Euclustions CAT / Assignment / Quiz / FAT / Project / Serviner					
10100	le of Evaluation: CAT / Assignment / Quiz / FAT / Project / Seminar					
List	of Challenging Experiments (Indicative)					
1.	Write a script to generate random test vectors for a given Verilog design.	3 hours				
2.	Write a script which reads a verilog design module and identifies whether it is	3 hours				
	a sequential or combinational design. Accordingly, the perl script should					
	generate the testbench file in verilog. Also, the input vectors from the					
	testbench should be in a randomized fashion.					
3.	Write a script that reads a set of log files from different simulation directories	2 hours				
	and generates a consolidated report in .xls format which should contain the					
	information of the test name, status and error messages. If the test is indicated					
	as successful in the log file, the status in the report should be as "TEST					
	PASSED" and if the test is unsuccessful, then the report should display the					
	status as "TEST FAILED".					
4.	Write a TCL Script which when executed should automatically compile your	3 hours				
	design modules and testbench modules and then perform the simulation. If the					
	simulation is successful, then the script should synthesize the design module.					
	The TCL script should also create a separate directory to dump the log files					
5	and a separate directory to write the netlist file.	2 hours				
5. 6	Write a script to perform netlist patching. Verification automation tool development using Perl/Python scripts	2 hours 2 hours				
6. Toto		15 hours				
	l Laboratory Hours le of evaluation: Continuous Assessment Test –I (CAT-I), Continuous Assessme					
	T-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative :					
	tions for industrial problems, Final Assessment Test (FAT).	ideas icading to				
-	ommended by Board of Studies 05-03-2019					
	roved by Academic Council No. 54 Date 14-03-2019					
<u>* •</u> PP						

Course code	Course Title	L T P J C
ECE 6024	VLSI Verification Methodologies	2 0 0 4 3
Pre-requisite	ECE5017 Digital Design with FPGA	Syllabus version
		v. 1.0
Course Objective:		
1. To introduce vari	ous verification techniques.	
2. To write Testbend	ch using System Verilog.	
	I test bench environment	
*		
Expected Course C	Outcome :	
The students will be	e able to :	
1. Comprehend the	VLSI verification techniques.	
2. Define classes and	-	
3. Develop design u	sing system verilog.	
	n environment using System Verilog.	
	A Verification environment.	
_	erification environment using UVM.	
	<u> </u>	
Module:1 Verifi	cation Techniques	4 hours
	rification - Testing Vs Verification - Verification Technolog	
	coverage – Functional coverage. Testbench – Linear Testbench	
	ecking Testbench – Regression - RTL Formal Verification.	
	6 6	
Module:2 Basic	OOP	3 hours
	Creating Object, object deallocation, copying objects, static	
variables, Inheritanc		
Module:3 Syster	m Verilog – Data Types & Procedural statements	6 hours
	tem Verilog – Literal values-data Types – Arrays – Array me	
	bedef – user defined structures – Enumerated types – attribu	
	edural statements and control flow - Processes in System Ve	_
	arguments – Returning from a routine	e
	<u> </u>	
Module:4 Conne	cting Testbench and Design	3 hours
	Stimulus timing, Module interactions, Connecting together,	
0	nvironment – Generator, Transactor, Driver, Monitor, Checker,	-
8		
Module:5 Rando	omization, Assertion and Coverage	3 hours
	system Verilog, Constraints, Functional coverage, cross covera	
Assertions	, , , , , , , , , , , , , , , , , , ,	8-, 8 ₁ -,
Module:6 Unive	rsal Verification Methodology	4 hours
	M - Verification components - Transaction level modeling	
Module:7 UVM	– Verification Environments	5 hours
	le verification components - Using Verification componen	
	n environment – Register classes.	
Module:8 Conte	emporary issues:	2 hours
	mporary mouch.	2 nours

	Total Lecture hours:	30 hours
Ref	erence Books:	
1.	Vanessa R. Copper, "Getting started with UVM: A Beginner's Guide", Verilab Pu Edition, 2013.	ıblishing, First
2.	Ray Salmei, "The UVM Primer: A Step-by-Step Introduction to the Universal V Methodology" Boston Light Press; First edition, 2013.	
3.	Christian B Spear, "System Verilog for Verification: A guide to learning the language features", Springer publications, Third Edition, 2012.	
4.	Janick Bergeron, "Writing Testbenches using System Verilog" Synopsys Publications, 2006.	Inc., Springer
Moo	le of Evaluation: CAT / Assignment / Quiz / FAT / Project / Seminar	
List	of Challenging Projects (Indicative)	
	 Develop a system Verilog testbench to verify your DUT by following the steps given i) Write the following blocks in system Verilog to verify your design a. Program Block b. Interface Block with clocking block and modport c. Top Level Harness file which has the instance of your DUT, test prointerface. ii) Develop the Generator, Transactor and Driver components for your DUT iii) Develop the self-checking feature by writing the receiver, monitor components for your DUT. iv) Simulate and verify the output. 	gram and the and checker
(CA	Define a packet class to encapsulate the packet information and create random part the generator then send, receive and check the correctness of the DUT using the for the given router IP. Follow the instructions given in the lab to complete the and verify the output for the good RTL code and the faulty code. Include cor- check the functional coverage is greater than 90%. The of evaluation: Continuous Assessment Test –I (CAT-I), Continuous Assessment T-II), Seminar / Challenging Assignments / Completion of MOOC / Innovative ide tions for industrial problems, Final Assessment Test (FAT).	packet objects task. Simulate vergroups and t Test –II
Rec	ommended by Board Of Studies 05-03-2019	
App	roved by Academic Council No. 54 Date 14-03-2019	

Course Code	Course title	L	Т	Р	J	С
ECE6025	LOW POWER IC DESIGN	2	0	0	4	3
Pre-requisite	ECE5015 - Digital IC Design					

Course Objective :

The course is aimed to

- 1. Understand the concepts and techniques of Low power VLSI.
- 2. Develop a broad insight into the methods used to confront the low power issue from lower level (circuit level) to higher levels (system level) of abstraction.
- 3. develop a system with multiple supply and threshold voltages used for low power DSP applications.

Expected Course Outcome :

After completion of the course student will be able to:

- 1. Understand the factors affecting the power in VLSI circuits.
- 2. Apply algorithmic and architectural level power optimization methods.
- 3. Apply logic and circuit level power optimization techniques.
- 4. Apply register transfer level power optimization techniques.
- 5. Develop an optimum code to reduce the power in the software level.
- 6. Analyse and explore the usage of sleep transistors for low power.
- 7. Develop power efficient IPs.

Module:1 Introduction to Low Power Design Methods

Motivation- Context and Objectives-Sources of Power dissipation in Ultra Deep Submicron CMOS Circuits – Static, Dynamic and Short circuit components Effects of scaling on power consumption-Low power design flow- Normalized Figure of Merit – PDP& EDP- Overview of power optimization at various levels.

Module:2 Algorithmic and Architecture Level Optimization

Pipelining and Parallel Processing approaches for low power in DSP filter structures- Multiple supply voltage and Multiple threshold voltage designs for low power- Computer arithmetic techniques for low power- Optimal drivers of high speed low power- software level power optimization.

Module:3 Logic Level and Circuit Level Optimization

5hours

3 hours

5hours

Theoretical background – Calculation of Steady state probability- Transition probability -Conditional probability- Transition density- Estimation and optimization of Switching activity-Power cost computation model.

Transistor variable re-ordering for power reduction- Low power library cell design (GDI)-Estimation of glitching power-leakage power optimization-Subthreshold logic design.

Module:4 Register Transfer Level Optimization 4 hours Low power clock-Interconnect and layout designs- Low power memory design and low power SRAM architectures- Clock gating- Bus Encoding techniques-Deglitching for low power.

Module:5Low Power Design of Sub-Modules5hoursCircuit techniques for reducing power consumption in Adders- Multipliers. Synthesis of FSM for

low power- Retiming	sequential	circuits	for low por	wer
iow power rectining	sequential	encuns	101 10 % p0	w 01.

Module:6	Sleep Transistor Design	3hours
Design met	trics- switch efficiency- area efficiency- IR drop, normal Vs reverse boo	dy bias -Layout
design of A	rea efficiency- Single row Vs double row- Inrush current and current late	ency.

Module:7 IP Design for Low Power

Architecture and partitioning for power gating- power controller design for the USB OTG- Issues in designing portable power controllers- clocks and resets- Packaging IP for reuse with power intent.

Module:8	Contemporary issues:	2 hours
	Total Lecture hours:	30hours
Text Book	(s)	
1. Jan M 2014.	Rabaey, MassoudPedram, Low power Design methodologies,SpringerU	S, First Edition,
	ik Roy, Sharat Prasad, Low Power CMOS VLSI circuit design, John Vecond Edition, 2010.	Wiley and Sons
Reference	Books	
	is, Dimitrios, ChristrianPignet, Goutis, Costas, Designing CMOS circuits er US, FirstEdition, 2011.	for low power,
2. Gary I	K.Yeap, Practical Low Power Digital VLSI Design, Springer US, First Ed	ition 2010.
3. AjitPa	1, Low Power VLSI circuits and Systems, Springer India, First Edition, 2	014.
Mode of E	Evaluation: Continuous Assessment Test -I (CAT-I), Continuous Asses	sment Test –I
(CAT-II),	Seminar / Challenging Assignments / Completion of MOOC / Innovativ	e ideas leading
to solution	s for industrial problems, Final Assessment Test (FAT).	
List of Pro	ojects (Indicative)	
1. Des	sign of Low Power, High Speed VLSI Adder and Multiplier Subsystems	
2. Pov	ver Gating Design solutions for Low Power	
3. Cir	cuit level power reduction using multi-Vt	
4. No:	n-conventional Low Power Circuits such as Energy Recovery Logic	
5. Des	sign of Low Power Clocking Solution for a Sequential System	
6. Lov	v power SRAM and CAM design	
7. Lov	v Power FFT Design for Wireless Communication Systems	
8. Lov	v Power Filter design for SDR systems.	
	valuation: Review I II & III	

Mode of Evaluation: Review I, II & II	Ι	
Recommended by Board of Studies	13-12-2015	
Approved by Academic Council	No. 40	18-03-2016

ECE6026		2 0 0 4 3
Pre-requisite	ECE5016-Analog IC Design	
Course Objecti		
The course is air		c.
	e the design aspects of dynamic analog circuits and analog-digital inte	erface
	cs in CMOS technology.	
2. Specify C	lesign implement ADC & DAC.	
Expected Cours	se Outcome ·	
· · · · · · · · · · · · · · · · · · ·	course the student will be able to	
	nd the theory of discrete-time signal processing and its implementation	on using
	chniques.	U
2. Realizing	g Sample and Hold Circuits using MOS by considering the non-ideality	ties.
•	CMOS based Switched Capacitor Circuits.	
	nding basics of Data Converters.	
•	the architectures of ADCs and DAC.	
	nd the oversampling converter architecture.	
/. Gain mix	ed-signal design experience using Cadence EDA tools.	
Introduction – s	npling ampling - Spectral properties of sampled signals - Oversampling – An	
Introduction – s design. Time In		nti-alias filter
Introduction – s design. Time In errors in Time In Module:2 San	ampling - Spectral properties of sampled signals - Oversampling – Anterleaved Sampling - Ping-pong Sampling System - Analysis of of nterleaved Sample and Hold. npling Circuits:	nti-alias filter fset and gain 3 hours
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Introduction – s design. Time In errors in Time In Module:2 San Sampling circui holds - Botton Characterizing S	 ampling - Spectral properties of sampled signals - Oversampling – And terleaved Sampling - Ping-pong Sampling System - Analysis of of the terleaved Sample and Hold. mpling Circuits: ts- Distortion due to switch - Charge injection - Thermal noise in the number of the sampling - Gate bootstrapped switch -Nakagome chample and hold - Choice of input frequency. 	nti-alias filter fset and gain 3 hours a sample and harge pump.
Introduction – s design. Time In errors in Time In Module:2 San Sampling circuit holds - Botton Characterizing S Module:3 Sw	 ampling - Spectral properties of sampled signals - Oversampling – And terleaved Sampling - Ping-pong Sampling System - Analysis of of interleaved Sample and Hold. npling Circuits: ts- Distortion due to switch - Charge injection - Thermal noise in n plate sampling - Gate bootstrapped switch -Nakagome chample and hold - Choice of input frequency. itched Capacitor Circuits: 	nti-alias filter fset and gain 3 hours a sample and harge pump. 4hours
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Module:6 Digital to Analog Converter Architectures:

5hours DAC spectra and pulse shapes - NRZ vs RZ DACs. DAC Architectures: Binary weighted -Thermometer DAC - Current steering DAC - Current cell design in current steering DAC -ChargeScaling DAC - Pipeline DAC.

Module:7	Oversampling Converter	••		7hours
Benefits of	Oversampling -Oversamp	oling with Noise Shapi	ng - Signal and Noi	se Transfer
Functions -	First and Second Order	Delta-Sigma Converters	. Introduction to Cont	inuous-time
	a Modulators - time-scalin			
	f Op-amp nonidealities - l		lealities - finite gain l	bandwidth -
Effect of A	DC and DAC nonidealities -	Effect of Clock jitter.		
M 1 1 0				
Module:8	Contemporary issues:			2hours
		Т	Cotal Lecture hours:	30hours
Text Book	(S)			
	Ohnhauser, Analog-Digita			
	ction to Digital-Analog Con			
	Johns and Ken Martin, An	alog Integrated Circuit	Design, John Wiley &	z Sons Inc.,
2012.				
Reference				·
	M.A.Ali, High Speed Da	ata Converters IET Ma	terials, Circuits & De	evices, First
	n, 2016. n,R. Schreier and Gabor.C.7	Famas Understanding D	alta Sigma Data Com	vortors
	Press, First Edition, 2017.	Temes, Understanding D	ena – Sigilia Data Colly	verters,
	valuation: Continuous Asses	sment Test –I (CAT-I)	Continuous Assessmen	t Test –II
	eminar / Challenging Assign			
• • • • •	for industrial problems, Fin	1		
Typical Pr		X	·	
1. Des	ign of Flash ADC			
	ign of High Speed Sample a	1		
	ign of Charge Pump Circuit.			
	ign of Switched Capacitor In	6		
	ign of Current – Steering DA	AC		
Mode of Ev	valuation :Review I, II & III			
	ded by Board of Studies	13-12-2015		
Recommen	ded by Dourd of Studies	10 12 2010		

ECE6027	Course Title I	I P J C
LCLOVE	RFIC DESIGN 2	2 0 0 4 3
Pre-requisite	ECE5016 - Analog IC Design	
Course Objecti		
The course is air		
1. 10 becon	ne familiarize with the design of integrated radio front-end circuits.	
Expected Cours	se Outcomes:	
-	e course the student should be able to	
	nd the concepts of RF IC Design.	
	nd the High Frequency model of MOS and importance of Impedance	Matching.
	the various transceiver and radio architectures.	U
•	ow Noise amplifiers and Mixers with specifications.	
5. Realize	COs and Frequency synthesizers and their applications to transceiver	design.
6. Classify	and comprehend the design of Power Amplifiers.	_
7. Gain RF	IC design experience in Cadence CAD tools.	
	roduction to RF & Wireless Technology:	5hour
	ign and applications - Choice of Technology - Basic concepts in	
Nonlinearly - Ti	me Variance - Intersymbol Interference - random processes - Noise. I	Definitions o
sensitivity - dyn	amic range -conversion Gain and Distortion.	
Module:2 Hig	the sequency Model of RF Transistors and Matching Networks:	41.
MOSFET behav	viour at RF frequencies - Noise performance and limitation of devices	- Impedance
MOSFET behav	viour at RF frequencies - Noise performance and limitation of devices rks - transformers and baluns.	
MOSFET behav matching netwo	rks - transformers and baluns.	- Impedance
MOSFET behav matching netwo Module:3 An	rks - transformers and baluns. alog& Digital Modulation for RF Circuits:	- Impedance
MOSFET behav matching netwo Module:3 An Coherent and N	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic	- Impedance 4hour s of Multiple
MOSFET behav matching netwo Module:3 An Coherent and N Access techniq	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic ues - Receiver and Transmitter Architectures and Testing: H	- Impedance 4hour s of Multiple leterodyne
MOSFET behaves matching networe Module:3 An Coherent and N Access techniq Homodyne, Ima	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic	- Impedance 4hour s of Multiple leterodyne
MOSFET behaves matching networe Module:3 An Coherent and N Access techniq Homodyne, Ima	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic ues - Receiver and Transmitter Architectures and Testing: H	- Impedance 4hour s of Multiple leterodyne
MOSFET behaves matching network matching network matching network matching network matching Module:3 An Coherent and N Access techniq Homodyne, Imatransmitters.	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic ues - Receiver and Transmitter Architectures and Testing: H ge-reject, Direct-IF and subsampled receivers - Direct Conversion a	- Impedance 4hour s of Multiple leterodyne nd two step
MOSFET behaves matching networes matching networes Module:3 An Coherent and N Access techniq Homodyne, Imatransmitters. Module:4 Lo	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic ues - Receiver and Transmitter Architectures and Testing: H ge-reject, Direct-IF and subsampled receivers - Direct Conversion a w Noise Amplifiers and Mixers	- Impedance 4hour s of Multiple leterodyne nd two step 4hour
MOSFET behave matching networ Module:3 An Coherent and N Access techniq Homodyne, Ima transmitters. Module:4 Lo Low Noise Am	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic ues - Receiver and Transmitter Architectures and Testing: H ge-reject, Direct-IF and subsampled receivers - Direct Conversion a w Noise Amplifiers and Mixers plifiers: Common Source LNA - Common Gate LNA -Cascode L	- Impedanc 4hour s of Multiple leterodyne nd two step 4hour
MOSFET behave matching networ Module:3 An Coherent and N Access techniq Homodyne, Ima transmitters. Module:4 Lo Low Noise Am	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic ues - Receiver and Transmitter Architectures and Testing: H ge-reject, Direct-IF and subsampled receivers - Direct Conversion a w Noise Amplifiers and Mixers	- Impedanc 4hour s of Multiple leterodyne nd two step 4hour
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MOSFET behave matching networ Module:3 An Coherent and N Access techniq Homodyne, Ima transmitters. Module:4 Lo Low Noise Am Design of Active Module:5 Vo	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic ues - Receiver and Transmitter Architectures and Testing: H ge-reject, Direct-IF and subsampled receivers - Direct Conversion a w Noise Amplifiers and Mixers plifiers: Common Source LNA - Common Gate LNA -Cascode L e and Passive Mixers.	- Impedance 4hour s of Multiple leterodyne nd two step 4hour NA. Mixers 3hour
MOSFET behave matching networ Module:3 An Coherent and N Access techniq Homodyne, Ima transmitters. Module:4 Lo Low Noise Am Design of Active Module:5 Vo Oscillators: Ba	alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic ues - Receiver and Transmitter Architectures and Testing: H ge-reject, Direct-IF and subsampled receivers - Direct Conversion a w Noise Amplifiers and Mixers uplifiers: Common Source LNA - Common Gate LNA -Cascode L e and Passive Mixers. Itage Controlled Oscillators and Frequency Synthesizers:	- Impedance 4hour s of Multiple leterodyne nd two step 4hour NA. Mixers 3hour er trade-off
MOSFET behav matching networ Module:3 An Coherent and N Access techniq Homodyne, Ima transmitters. Module:4 Lo Low Noise Am Design of Active Module:5 Vo Oscillators: Ba Resonatorless V	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic ues - Receiver and Transmitter Architectures and Testing: H ge-reject, Direct-IF and subsampled receivers - Direct Conversion a w Noise Amplifiers and Mixers plifiers: Common Source LNA - Common Gate LNA -Cascode L e and Passive Mixers. Itage Controlled Oscillators and Frequency Synthesizers: sic topologies VCO and definition of phase noise. Noise-Pow /CO design - Quadrature and single-sideband generators - Radie	- Impedance 4hour s of Multiple leterodyne nd two step 4hour NA. Mixers 3hour er trade-off
MOSFET behav matching netwo Module:3 An Coherent and N Access techniq Homodyne, Ima transmitters. Module:4 Lo Low Noise Am Design of Active Module:5 Vo Oscillators: Ba Resonatorless V Synthesizers: PI	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic ues - Receiver and Transmitter Architectures and Testing: H ge-reject, Direct-IF and subsampled receivers - Direct Conversion a w Noise Amplifiers and Mixers plifiers: Common Source LNA - Common Gate LNA -Cascode L e and Passive Mixers. Itage Controlled Oscillators and Frequency Synthesizers: sic topologies VCO and definition of phase noise. Noise-Pow /CO design - Quadrature and single-sideband generators - Radio Ls.	- Impedance 4hour s of Multiple leterodyne nd two step 4hour NA. Mixers 3hour er trade-off o Frequency
MOSFET behav matching networ Module:3 An Coherent and N Access techniq Homodyne, Ima transmitters. Module:4 Lo Low Noise Am Design of Active Module:5 Vo Oscillators: Ba Resonatorless V Synthesizers: PI	rks - transformers and baluns. alog& Digital Modulation for RF Circuits: on coherent detection - Mobile RF Communication systems and basic ues - Receiver and Transmitter Architectures and Testing: H ge-reject, Direct-IF and subsampled receivers - Direct Conversion a w Noise Amplifiers and Mixers plifiers: Common Source LNA - Common Gate LNA -Cascode L e and Passive Mixers. Itage Controlled Oscillators and Frequency Synthesizers: sic topologies VCO and definition of phase noise. Noise-Pow /CO design - Quadrature and single-sideband generators - Radie	- Impedance 4hour s of Multiple leterodyne nd two step 4hour NA. Mixers 3hour er trade-off

Module:7 Radio architectures:

GSM radio architectures, CDMA, UMTS radio architectures.

Mo	dule:8	Contemporary issues:			2hours
			Total Lecture hours:		30hours
Tex	xt Book((s)			
1.	B.Raza	avi, RF Microelectronics, Pea	rson Education Limited, S	econd Edition, 2013.	
2.					
Ref	ference 1	Books			
1.	Gu, Q 2010	izheng, RF System Design o	of Transceivers for Wirel	ess Communications,	Springer,
2.	Bosco	Leung, VLSI for Wireless Co	ommunication, Springer, S	econd Edition, 2011	
Mo	de of E	valuation:Continuous Assess	ment Test -I (CAT-I), C	Continuous Assessmer	nt Test –II
(CA	AT-II), S	Seminar / Challenging Assign	ments / Completion of M	OOC / Innovative ide	as leading
to s	olutions	for industrial problems, Fina	l Assessment Test (FAT).		
Lis		jects(Indicative)			
		Characterisation study of RF	device/circuit		
		ign of Low Noise Amplifier			
		ign of Voltage Controlled Os	cillators		
		ign of Power Amplifiers			
		ign and Implement- any one of	of the Receiver architectur	e	
Mo	de of Ev	aluation: Review I, II & III	1		
Rec	commen	ded by Board of Studies	13-12-2015		
Ap	proved b	y Academic Council	No. 40	18-03-2016	

Course Code	Course Title	LT	P J	_
ECE6028	NANOSCALE DEVICES AND CIRCUIT DESIGN	2 0	04	3
Pre-requisite	ECE5018 - Physics of VLSI Devices			
~				
Course Objecti				
The course is	s aimed to			
1. Make stu	ident to understand CMOS scaling			
	nd theory and operation of multigate MOSFET and analog design dig	gital, c	ircuit	5
	Itigate devices aterials and their properties used for designing Micros			
3. understar	nd the concepts of Microsystem technologies used for realizing Micr	osenso	ors and	b
actuators				
	nd the working principles of Interface Electronic Circuits for resistive	e, cap	acitive	•
and temp	perature sensors.			
Europeted Car	a Outromo .			
Expected Cours	course the students will be able to			
	nd the CMOS scaling			
	the need of novel MOSFET.			
	the physics of multigate MOS system			
	nowire FETs.			
5. Design d	igital and analog circuit using multigate devices.			
6. Understa	nd the physics of CNTFET			
7. Develop	analytical model for novel FETs and validate them by numerical sin	nulatio	ons	
	CMOS Scaling Issues and Solutions		2ho	ours
MOSFET scalin	ng, short channel effects, quantum effects, volume inversion, thr	eshold	2h o volta	age,
MOSFET scalin channel engine	ng, short channel effects, quantum effects, volume inversion, threering, source/drain engineering, high-k dielectric, strain engine	eshold	2h o volta	age,
MOSFET scalin	ng, short channel effects, quantum effects, volume inversion, threering, source/drain engineering, high-k dielectric, strain engine	eshold	2h o volta	age,
MOSFET scalin channel engined technology mob	ng, short channel effects, quantum effects, volume inversion, threering, source/drain engineering, high-k dielectric, strain engineering, gate stack.	eshold	2h l volta multig	age, gate
MOSFET scalin channel engined technology mob	ng, short channel effects, quantum effects, volume inversion, threering, source/drain engineering, high-k dielectric, strain engine ility, gate stack.	eshold ering,	2hc l volta multig 2hc	age, gate
MOSFET scalin channel engined technology mob Module:2 I SOI MOSFET,	ng, short channel effects, quantum effects, volume inversion, threering, source/drain engineering, high-k dielectric, strain engine ility, gate stack. ntroduction to Novel MOSFETs multigate transistors, single gate, double gate, triple gate, surrour	eshold ering,	2hc l volta multig 2hc	age, gate
MOSFET scalin channel engined technology mob	ng, short channel effects, quantum effects, volume inversion, threering, source/drain engineering, high-k dielectric, strain engine ility, gate stack. ntroduction to Novel MOSFETs multigate transistors, single gate, double gate, triple gate, surrour	eshold ering,	2hc l volta multig 2hc	age, gate
MOSFET scalin channel engined technology mob Module:2 I SOI MOSFET, Nanowire transis	ng, short channel effects, quantum effects, volume inversion, threering, source/drain engineering, high-k dielectric, strain engine ility, gate stack. ntroduction to Novel MOSFETs multigate transistors, single gate, double gate, triple gate, surrour stors	eshold ering,	2hc l volta multig 2hc e, Sili	age, gate ours con
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MOSFET scalin channel enginer technology mob Module:2 I SOI MOSFET, Nanowire transis Module:3 F MOS electrosta	ng, short channel effects, quantum effects, volume inversion, threering, source/drain engineering, high-k dielectric, strain engine ility, gate stack. ntroduction to Novel MOSFETs multigate transistors, single gate, double gate, triple gate, surrour stors Physics of Multi-gate MOS System	eshold ering, id gat	2hc l volta multia 2hc e, Sili 5hc tem, a	age, gate ours con ours gate
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MOSFET scalin channel enginer technology m→ Module:2 I SOI MOSFET, Nanowire transis Module:3 F MOS electrosta voltage effect, s tunnel current, ty Module:4 N	ng, short channel effects, quantum effects, volume inversion, threering, source/drain engineering, high-k dielectric, strain engineering, gate stack. Introduction to Novel MOSFETs multigate transistors, single gate, double gate, triple gate, surrour stors Physics of Multi-gate MOS System tics, 1D, 2D MOS electrostatics, ultimate limits, double gate MO emiconductor thickness effect, asymmetry effect, oxide thickness effect, asymmetry effect, oxide thickness effect, asymmetry effect, oxide thickness effect, so dimensional confinement, scattering Nanowire FETS re MOSFETs, evaluation of I-V characteristics, I-V c	eshold ering, id gat S sys effect	2hc l volta multia 2hc e, Sili 5hc for r	age, gate ours con ours gate rron ours ion-
MOSFET scalin channel enginer technology mob Module:2 I SOI MOSFET, Nanowire transis Module:3 F MOS electrosta voltage effect, s tunnel current, tr Module:4 N Silicon nanowi degenerate carr	ng, short channel effects, quantum effects, volume inversion, threering, source/drain engineering, high-k dielectric, strain engine ility, gate stack. ntroduction to Novel MOSFETs multigate transistors, single gate, double gate, triple gate, surrour stors Physics of Multi-gate MOS System tics, 1D, 2D MOS electrostatics, ultimate limits, double gate MC emiconductor thickness effect, asymmetry effect, oxide thickness effect wo dimensional confinement, scattering Nanowire FETS re MOSFETs, evaluation of I-V characteristics, I-V character ier statistics, I-V characteristics for degenerate carrier statistic	eshold ering, id gat S sys effect	2ho l volta multia 2ho e, Sili 5ho tem, g , elect	age, gate ours con ours gate rron ours ion-
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MOSFET scaling channel engined technology mobility Module:2 I SOI MOSFET, Nanowire transis Module:3 I MOS electrosta voltage effect, s tunnel current, transis Module:4 N Silicon nanowidegenerate carr conduction in mage Module:5 I Digital circuits	ng, short channel effects, quantum effects, volume inversion, threering, source/drain engineering, high-k dielectric, strain engineering, gate stack. Introduction to Novel MOSFETs multigate transistors, single gate, double gate, triple gate, surrour stors Physics of Multi-gate MOS System tics, 1D, 2D MOS electrostatics, ultimate limits, double gate MC emiconductor thickness effect, asymmetry effect, oxide thickness effect, asymmetry effect, oxide thickness effect asymmetry effects, I-V characteristics, I-V characteristics for degenerate carrier statistic olecules, general model for ballistic nano transistors, CNT-FETs Digital Circuit Design using Multi-gate Devices	eshold eering, ad gat S sys effect	2hc l volta multig 2hc e, Sili 5hc for t electro 5hc	age, gate

Analog circuit design, trans-conductance, intrinsic gain, flicker noise, self-heating, band gap voltage reference, operational amplifier, comparator designs, mixed signal, successive approximation DAC, RF circuits

Module:7	Carbon Nanotube FET	4hours						
CNT-FET, CNT memories, CNT based switches, logic gates, CNT based RF devices, CNT based								
RTDs, CNTFET based applications								
Module:8	Contemporary issues	2 hours						

		Total Lec	ture hours:	30hours				
Text	Text Book(s)							
1.	J P Colinge, FINFETs and other Multi-gate Transistors, Springer, Germany, 2010.							
2.	B.G.Park, S.W. Hwang &Y.J.Park, Nanoelectronic Devices, Pan Stanford Publisher							
	Singapore, 2012.							
Reference Books								
1.	N. Collaert, CMOS Nanoelectronics: Innovative Devices, Architectures and Applications,							
	Reprint Pan Stanford publisher, Singapore, 2012.							
2.	Niraj K. Jha, Deming Chen, Nanoelectronic Circuit Design, Springer London, First Edition,							
	2011.							
Mode of Evaluation: Continuous Assessment Test -I (CAT-I), Continuous Assessment Test -II								
(CAT-II), Seminar / Challenging Assignments / Completion of MOOC / QUIZ, Final Assessment								
Test	Test (FAT).							
List	List of Projects							
1. Design and Extraction of DC and AC parameters of MOSFET with Source/Drain Extension								
2. Performance Analysis of Double/Triple/Surround gate devices								
3	3. Analysis of Gate Work Function Engineering in Multi-gate Devices							
4	4. Single Event Upset/Soft Error Analysis in Multi-gate FETs							
-	5. Comparison of CMOS and Fin FET based SRAM							
	6. Design of OTA and Comparator in Multi-gate Devices							
	Mode of Evaluation:Review I, II & III							
Reco	ommended by Board of Studies	13-12-2015						
App	Approved by Academic CouncilNo. 4018-03-2016							